

Nano-carbon structures for electronic applications?

1st Ireland SummerSchool 2011

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Nanodevices
(CRANN)



Outline

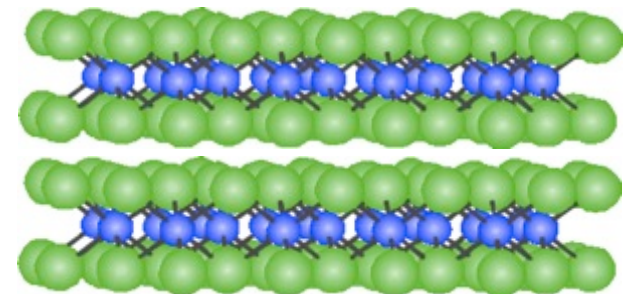
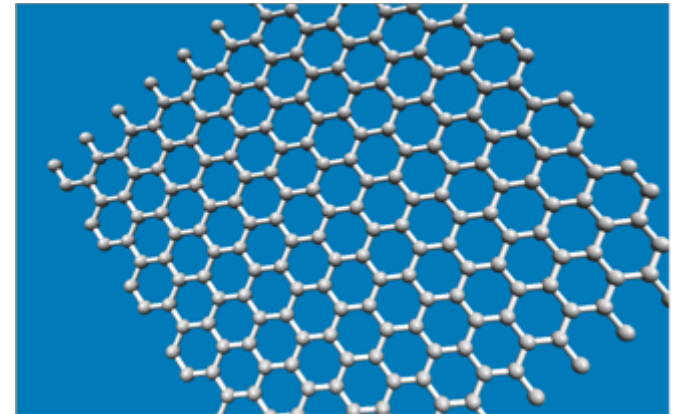
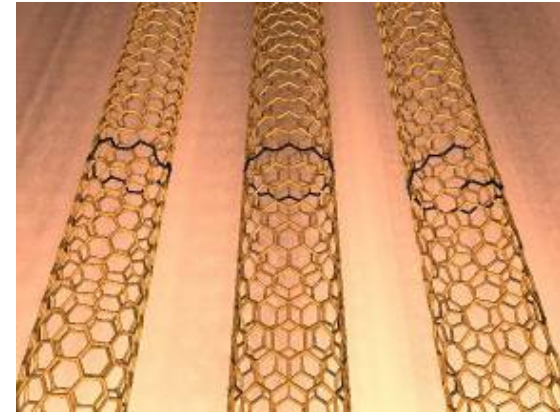


- ▶ Carbon Nano-structures: Applications in microelectronics
- ▶ Vertical Carbon devices
- ▶ Graphene Processing
- ▶ Other 2D Materials
- ▶ Carbon NEMS?
- ▶ Conclusions

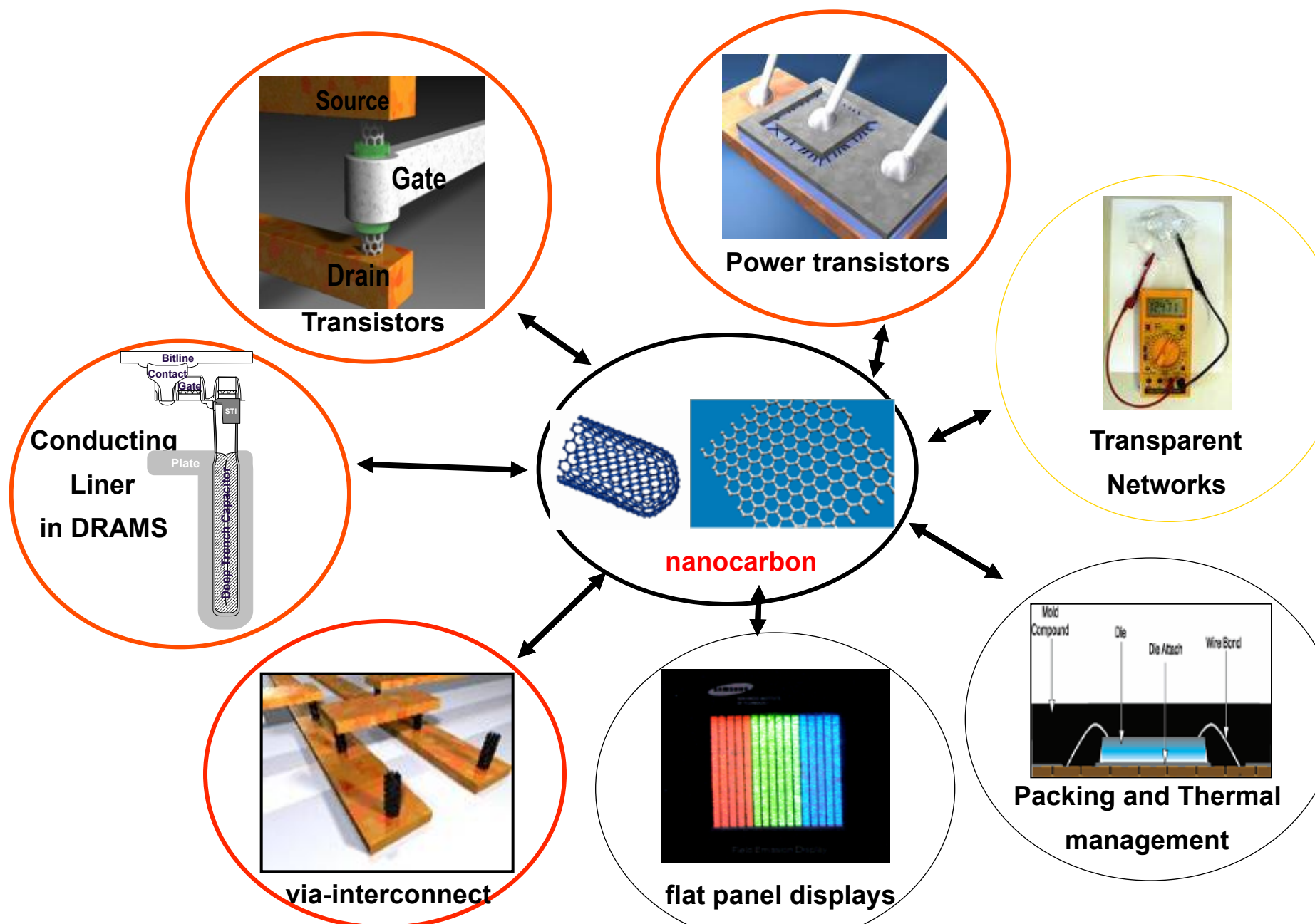


Graphene and Nanotubes – Unique Properties

- High Mobilities – Ballistic conductance, massless Dirac fermions in graphene
- High Thermal Conductivity
- Room Temperature Quantum Effects
- Tuneable Band Gaps
- High surface area
- Chemically inert
- Mechanically stable

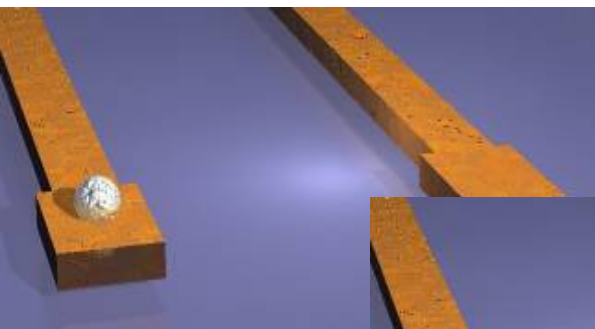


Potential Applications for Carbon Nanostructures in electronics

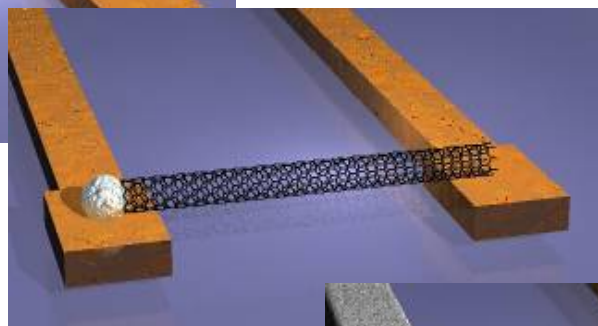




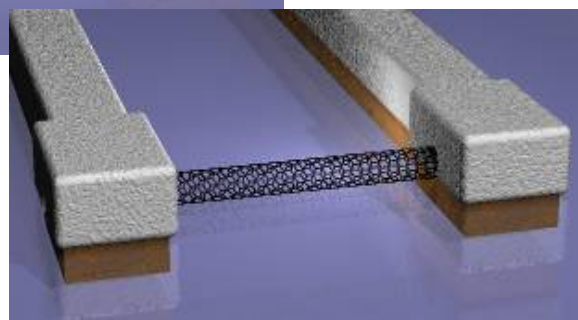
Lateral CNTFETs – process flow



Structure metal contacts and Catalyst on wafer scale

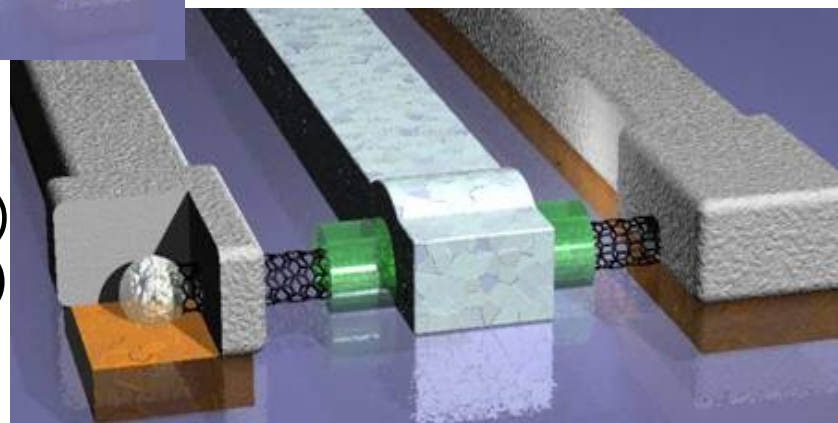


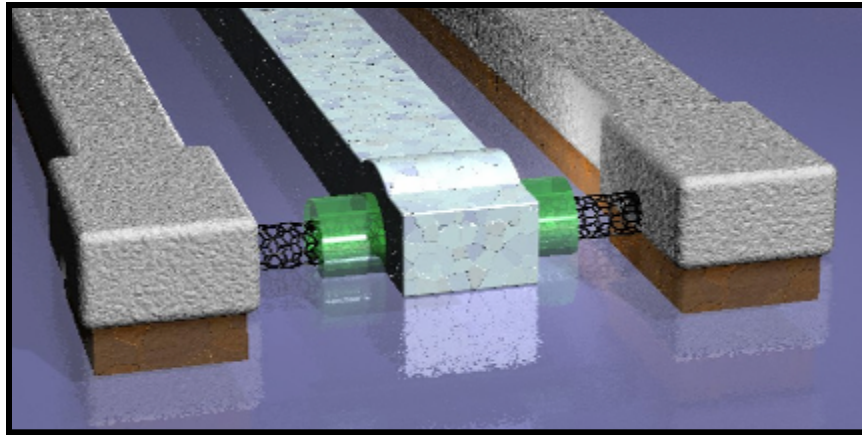
Deposition by drop casting or CVD – **random process!**



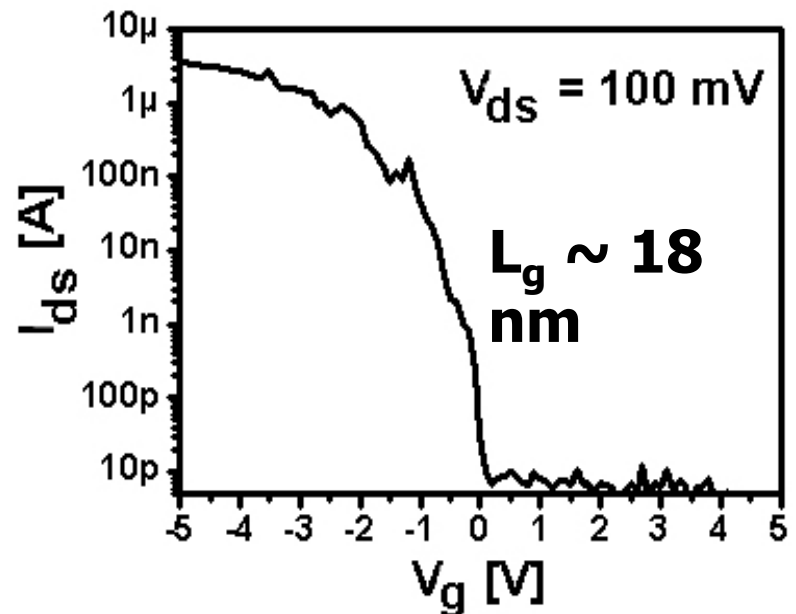
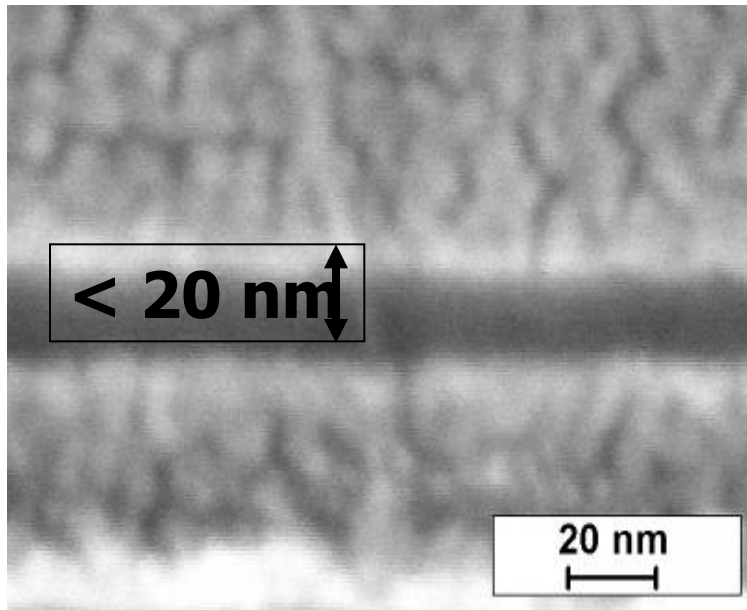
Encapsulate CNT and Contact by electroless deposition

Apply Dielectric (Dip Coat Process!) and Top Gate (**E-beam lithography**)



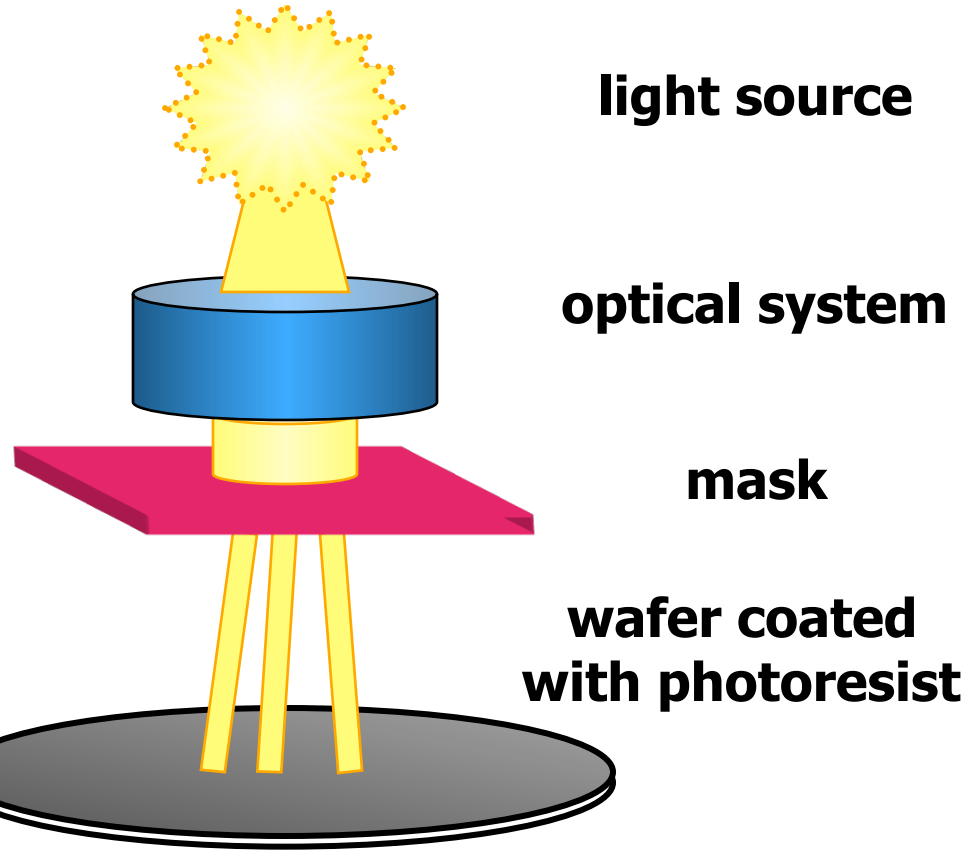


- ⇒ Works at channels shorter 20 nm!
- Ballistic regime
- ⇒ Ultra high currents can be switched ($I_{on} > 10 \mu\text{A}/\text{tube}$)
- ⇒ On/off ratio $> 10^5$

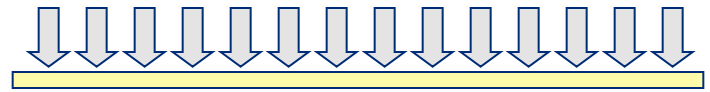




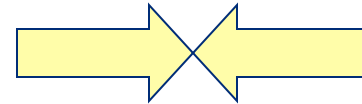
Power of silicon processing and lithography



Parallel Processing

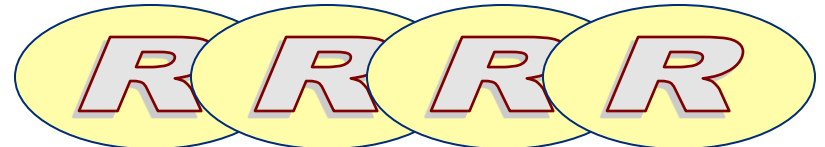


Lateral Scaling



Reproducibility

good process control high yield



Throughput –

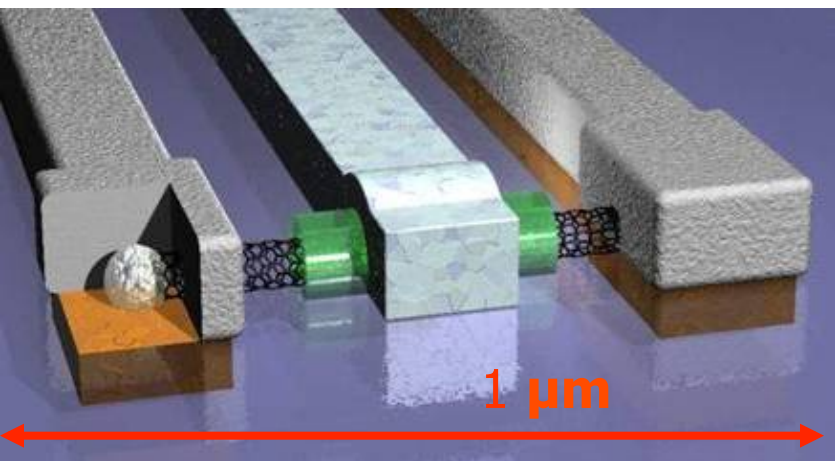
the number of wafers per hour optical lithography → **60 - 90** wafers/hour



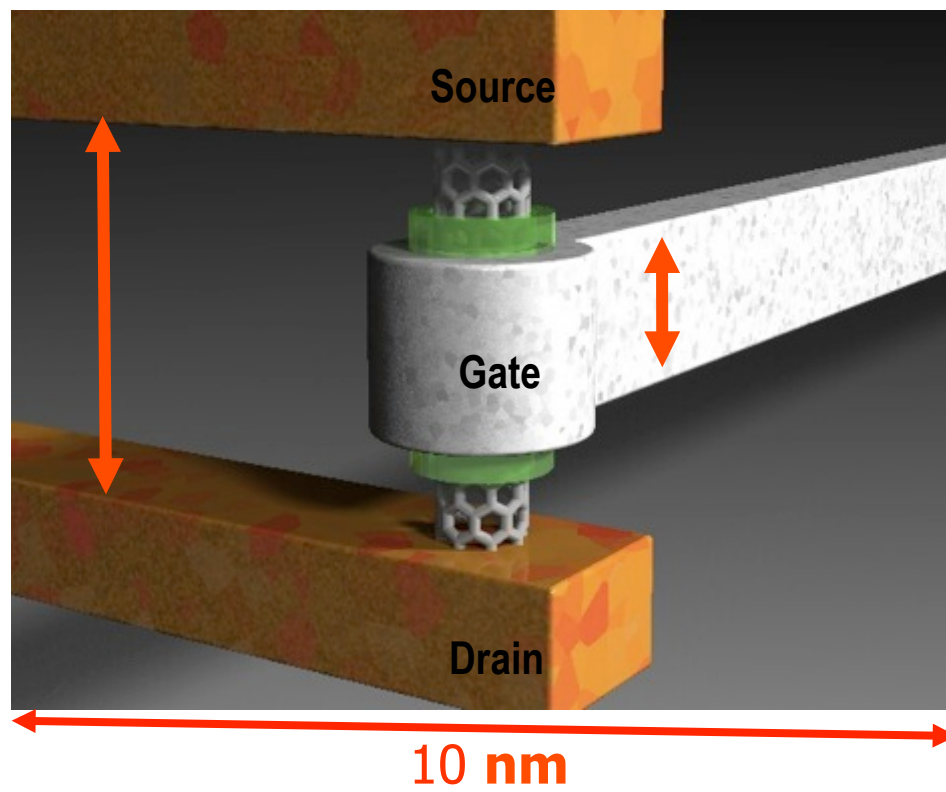
Limitations of lateral CNTFET approach



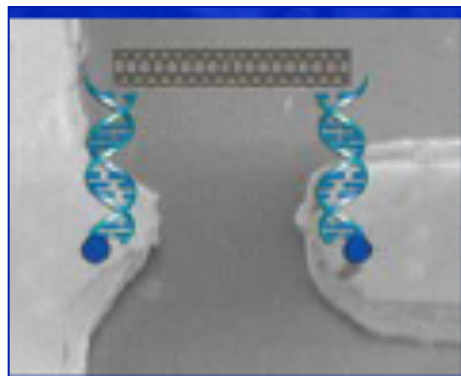
Lateral dimensions?



The vertical CNTFET could be the solution – but there is still a long way to go....

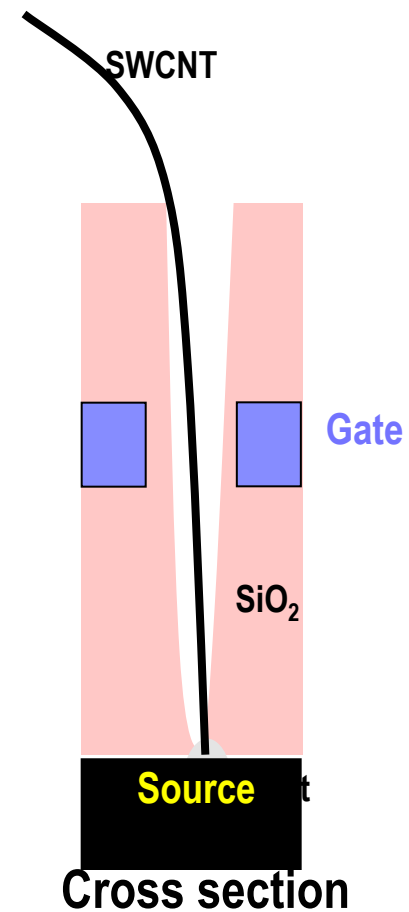
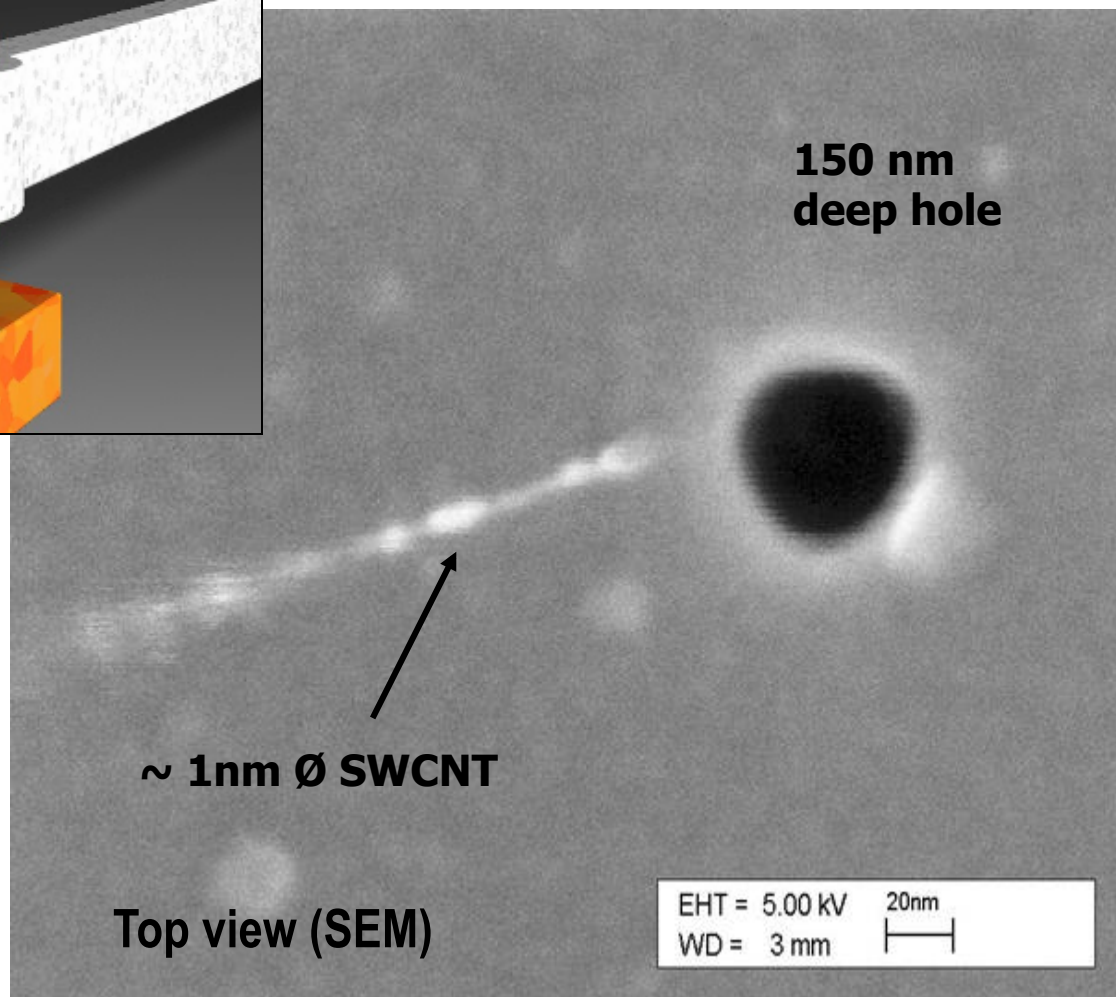
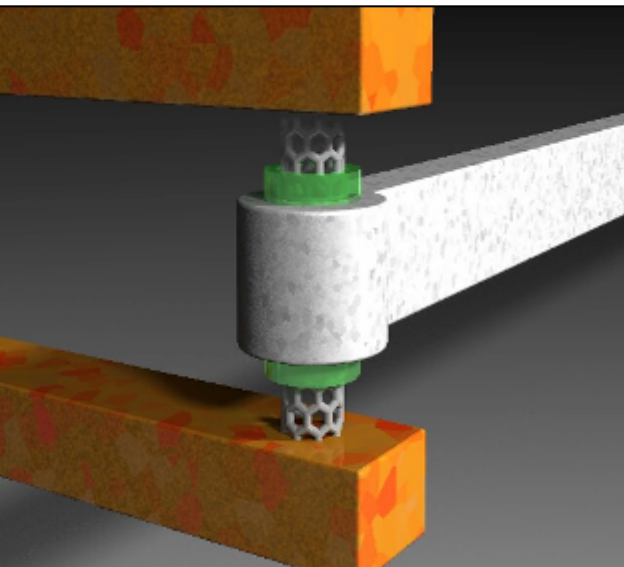


Accurate Positioning of CNTs ?



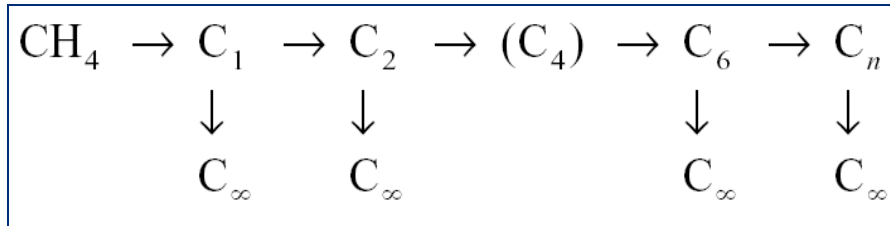
metal gate length can be adjusted to sub-nm accuracy by deposition

The vertical transistor concept

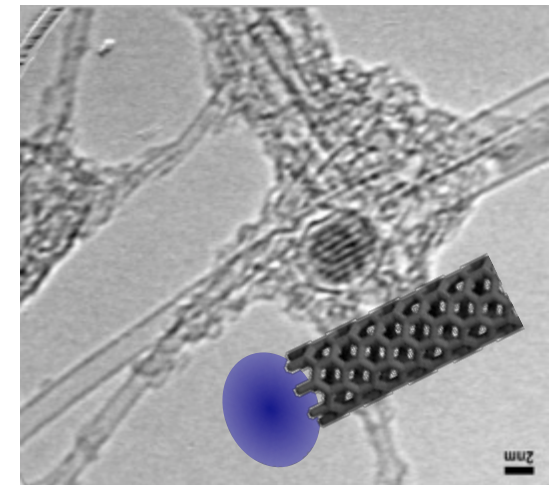
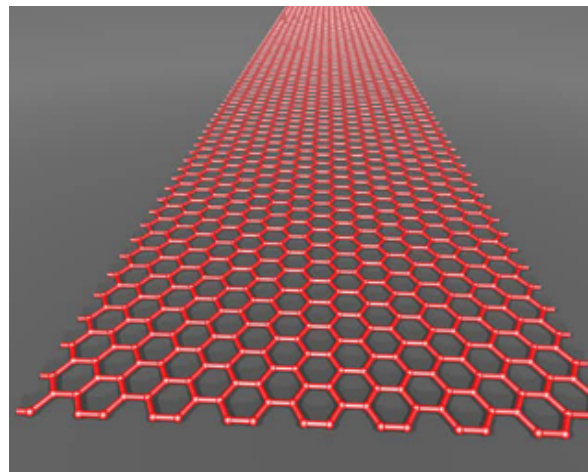
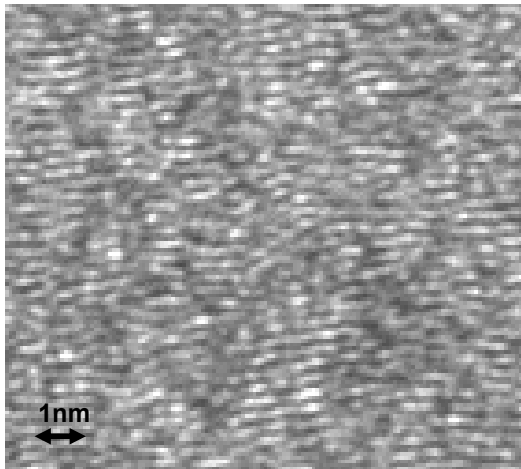




CVD of nano-carbon structures



Pyrolysis of hydrocarbons



Pyrolytic Carbon (PyC)

Graphene by CVD

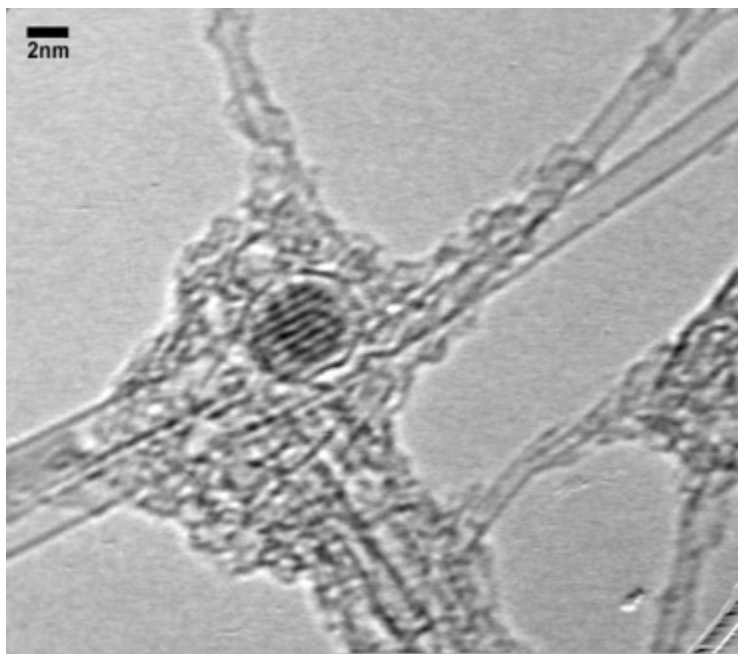
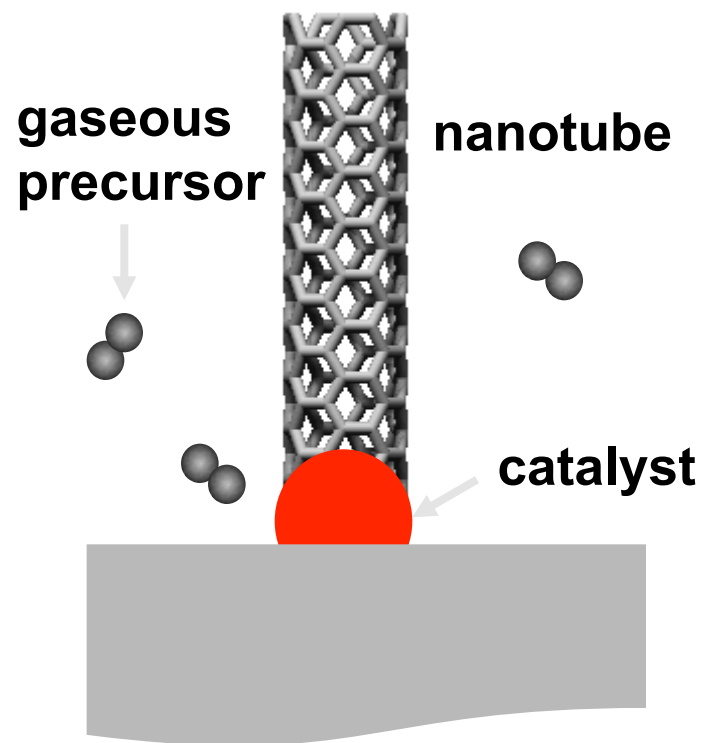
CNTs by CVD



Challenge: Structural homogeneity of CVD CNTs



**Bottom-up
(nanotubes, nanowires)**



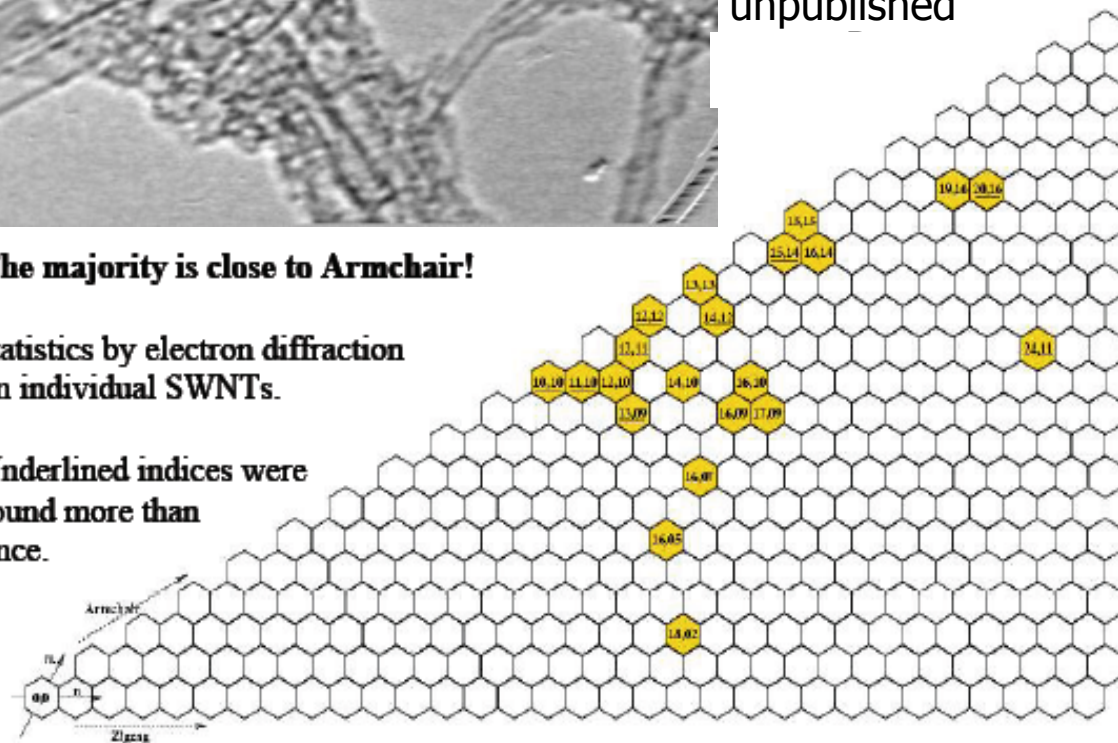
Lattice fringes match with walls of SWCNT a MoCo-Catalyst

J. C. Meyer, G.S Duesberg et al. , unpublished

The majority is close to Armchair!

statistics by electron diffraction on individual SWNTs.

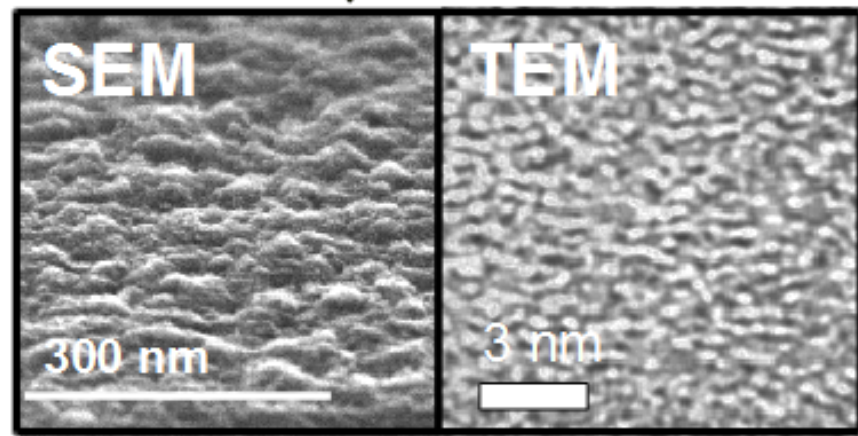
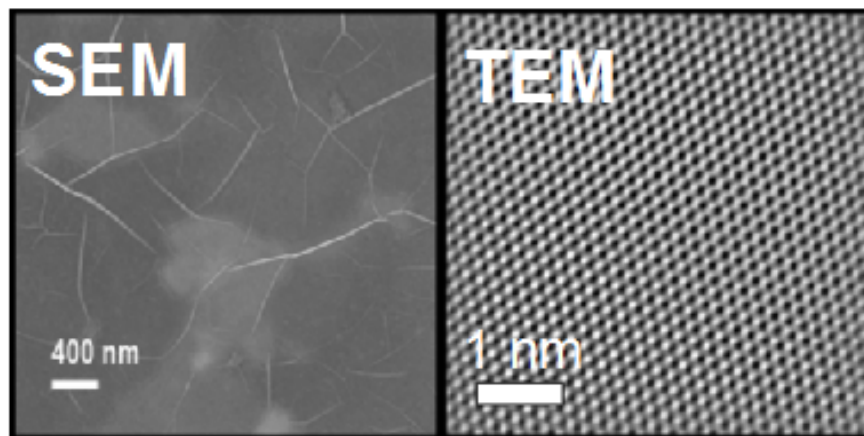
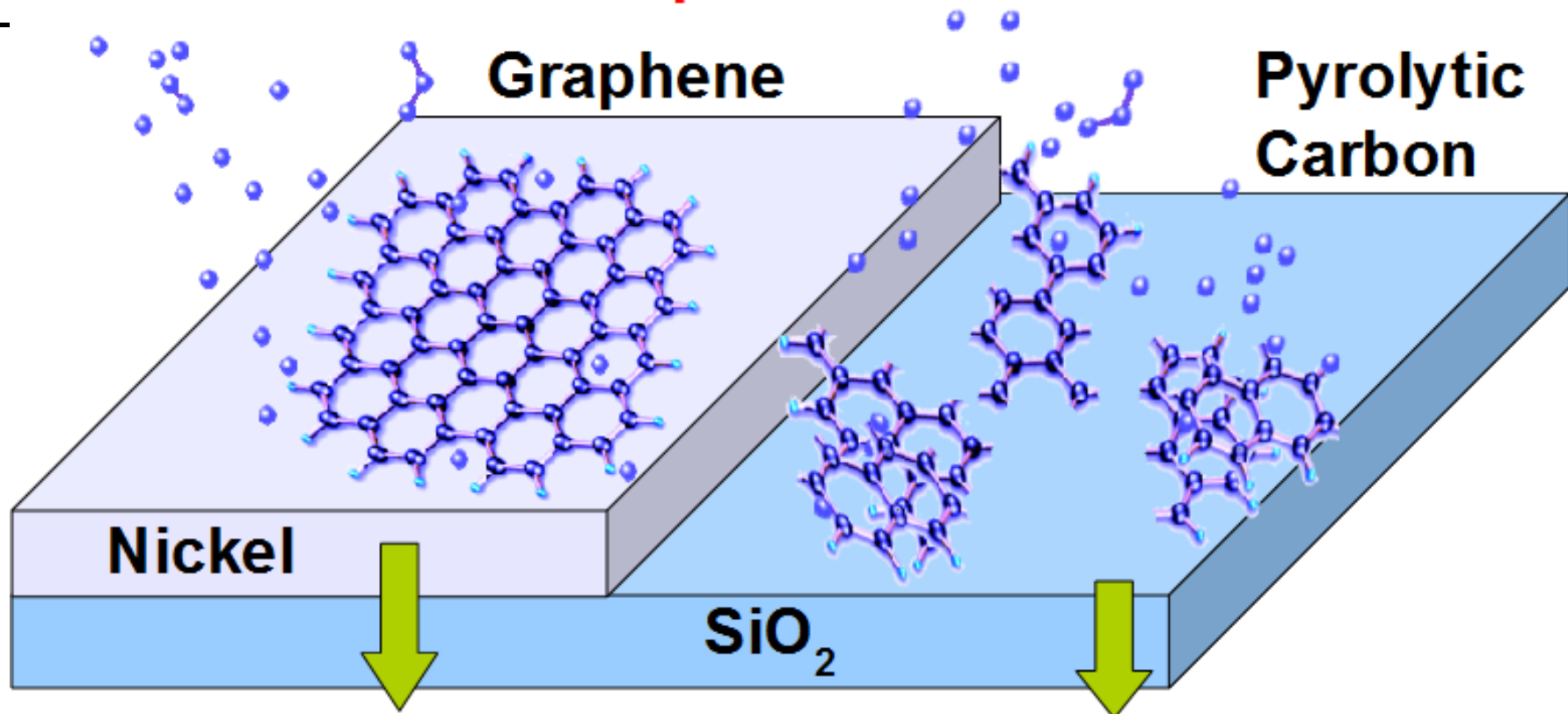
Underlined indices were found more than once.



**self-organized 1-D structures
high perfection**

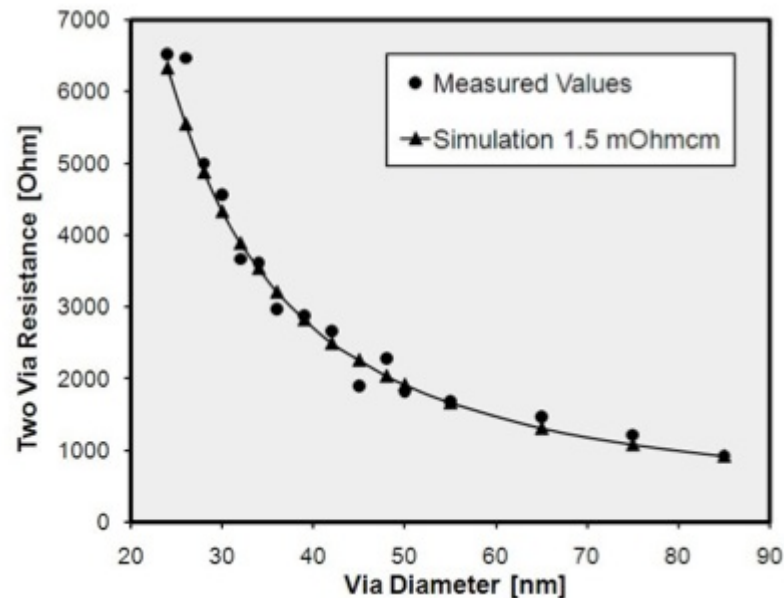
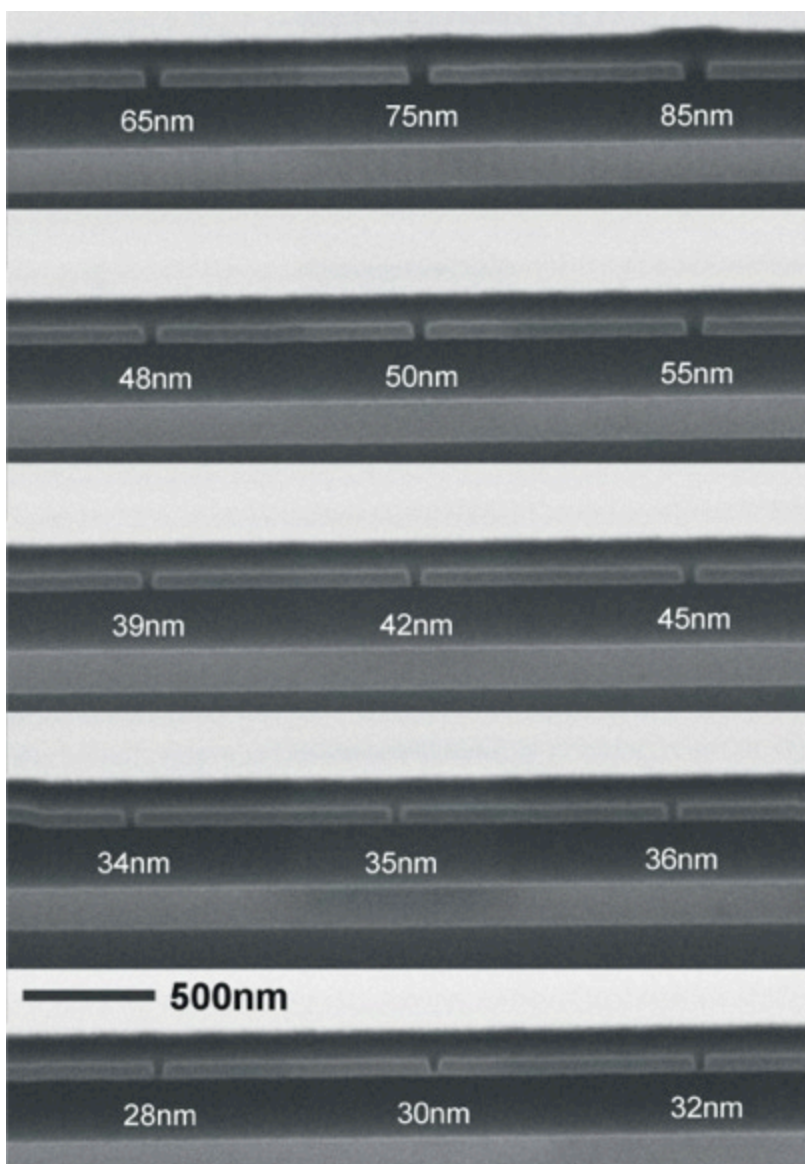


Hetero-epitaxial CVD





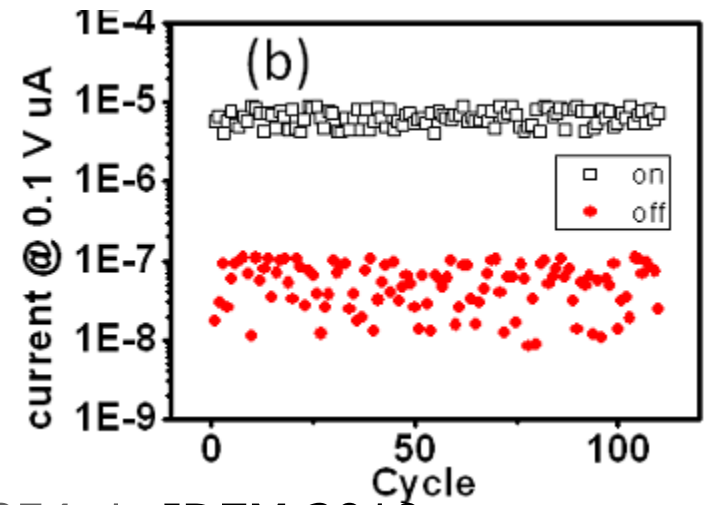
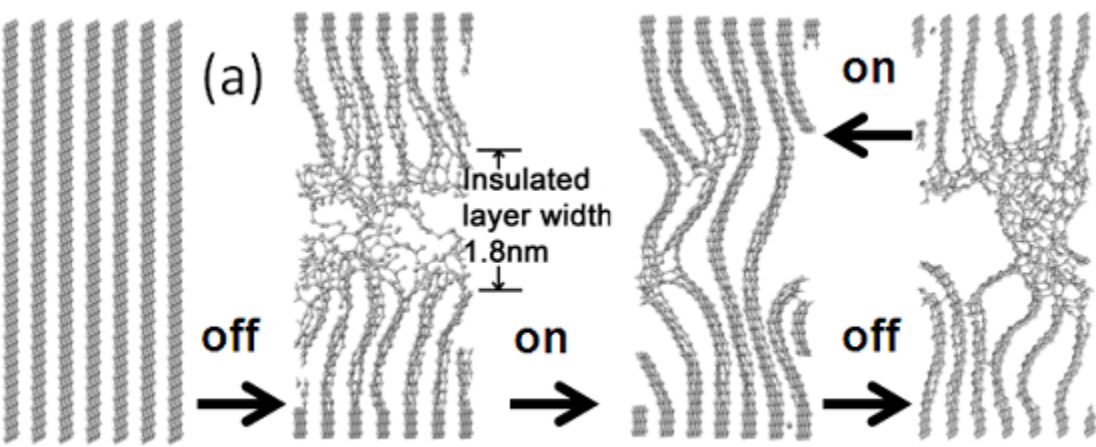
Carbon Interconnects – PyC and CNTs



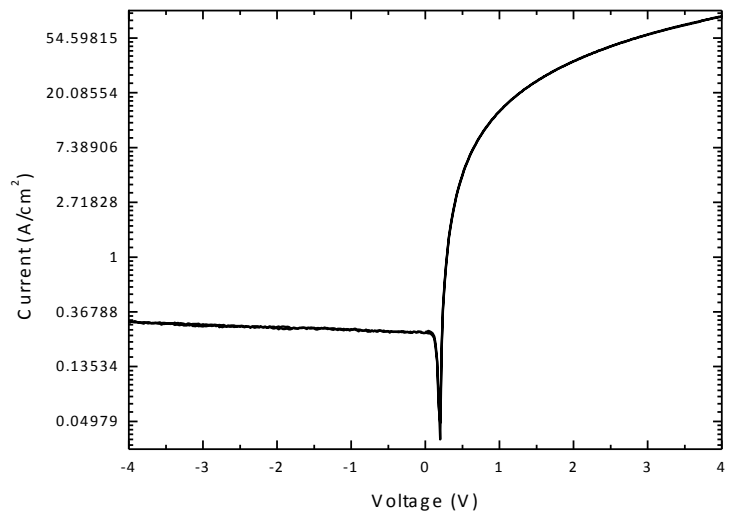
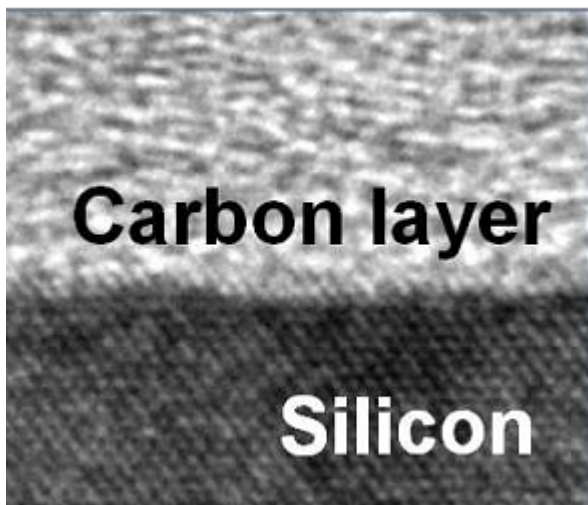
A. Graham, G. Schindler, G. S. Duesberg, T. Lutz, and W. Weber, Journal of Applied Physics, 107 114316.2010.



Carbon devices: Memory and diode



Carbon CB Ram: Kreupl et al. [arXiv:1012.4854v1](https://arxiv.org/abs/1012.4854v1), IDEM 2010



Schottky diode: Duesberg, Kreupl, Graham et al.



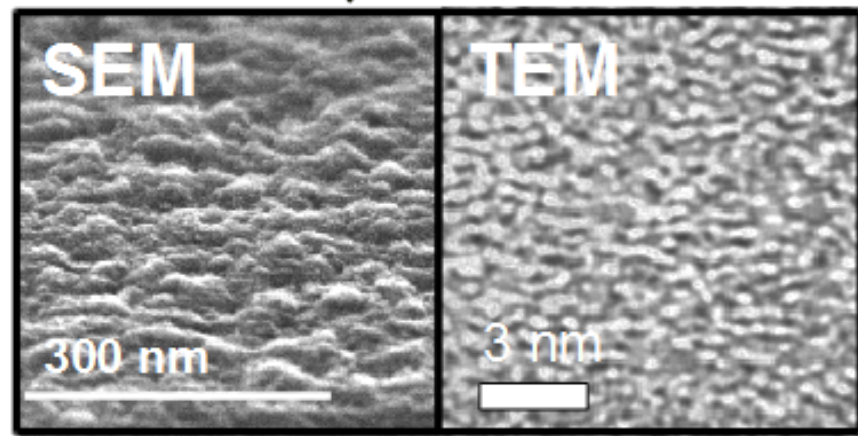
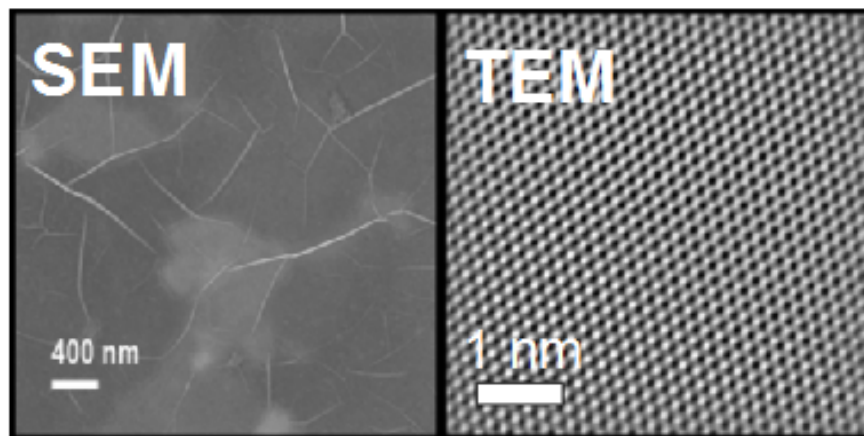
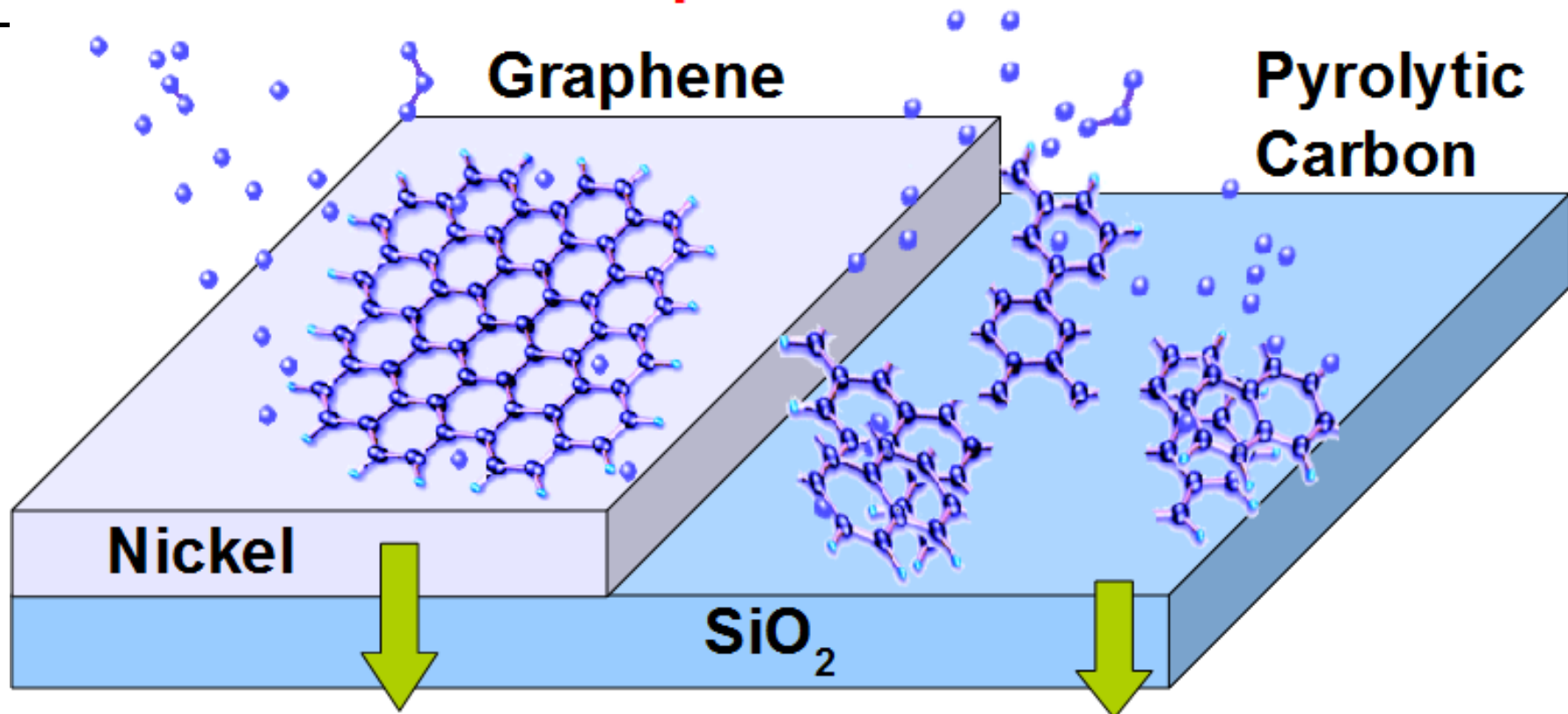
Outline

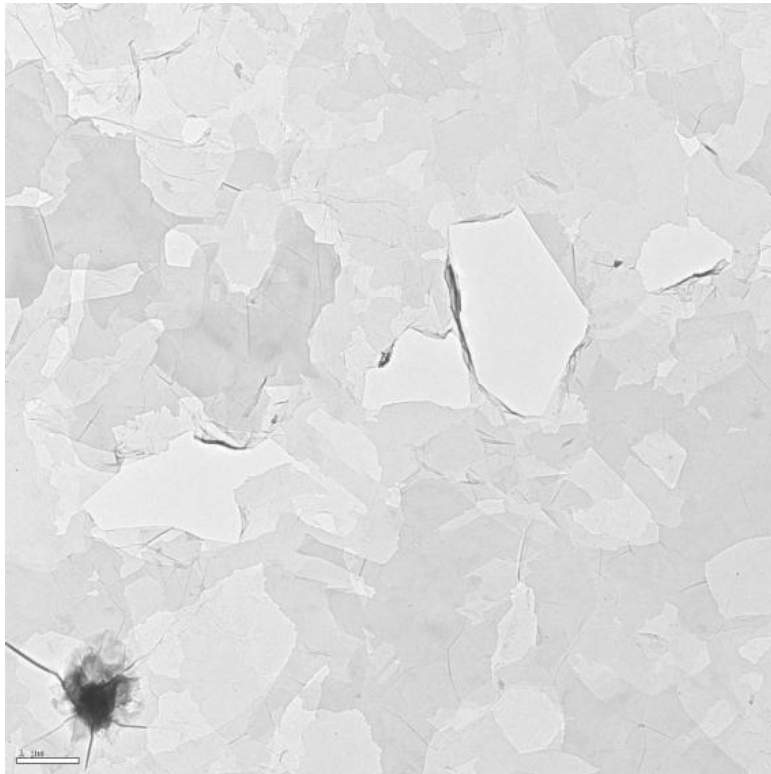


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- ▶ **Graphene Processing**
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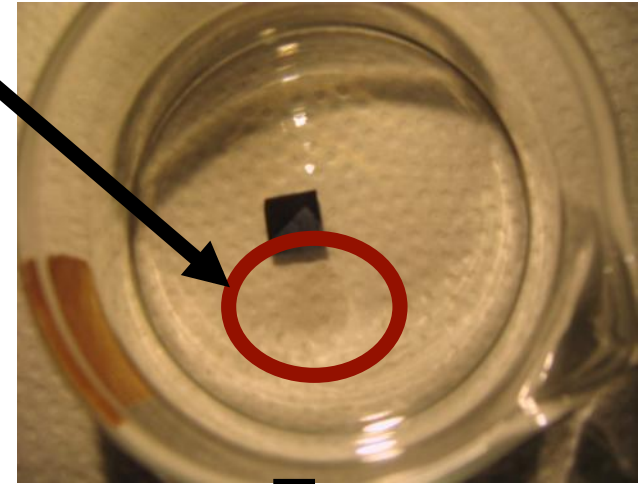
Hetero-epitaxial CVD





SEM

Graphene

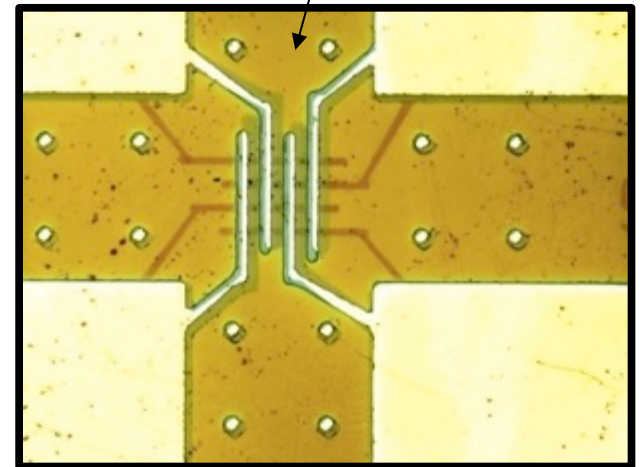
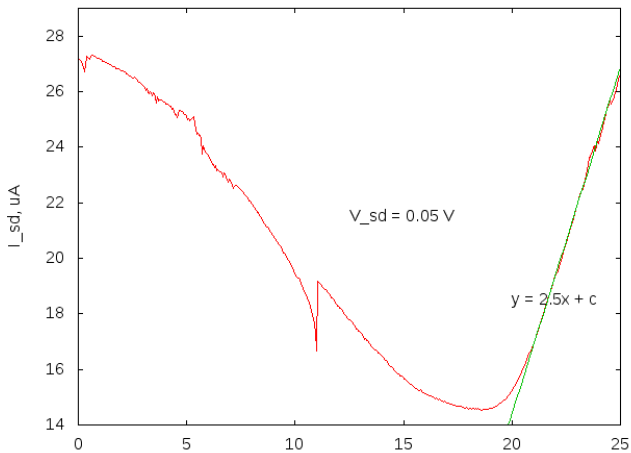
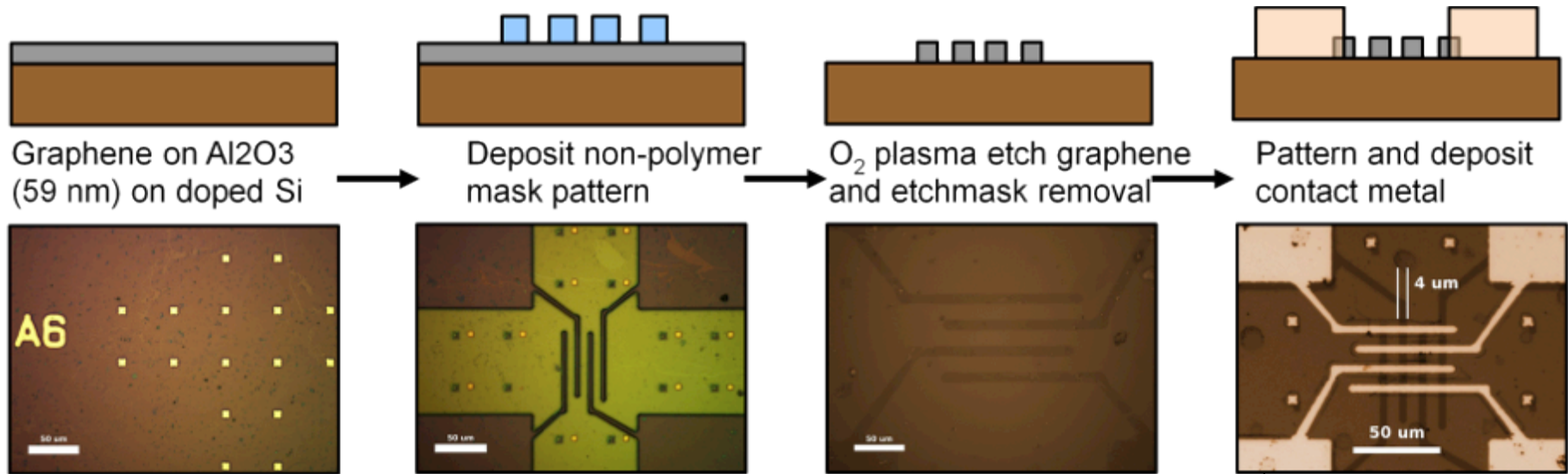


- Optical images of graphene films transferred to glass slides

S. Kumar et al. Chem Comm 2010



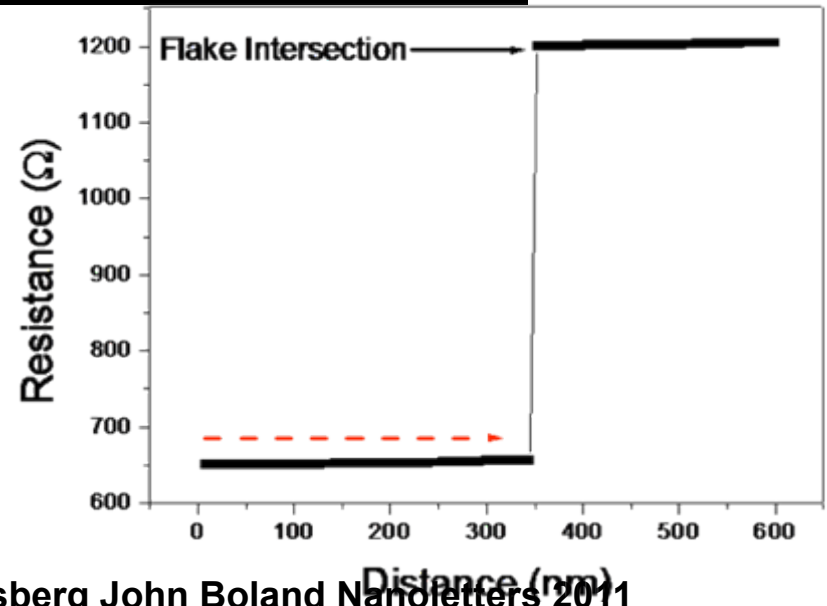
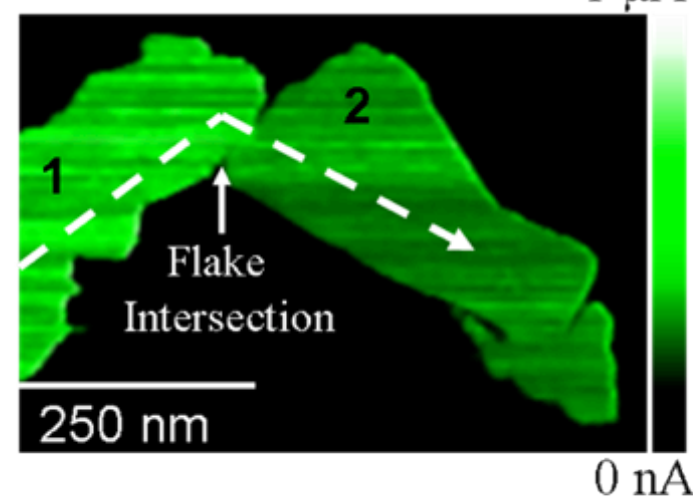
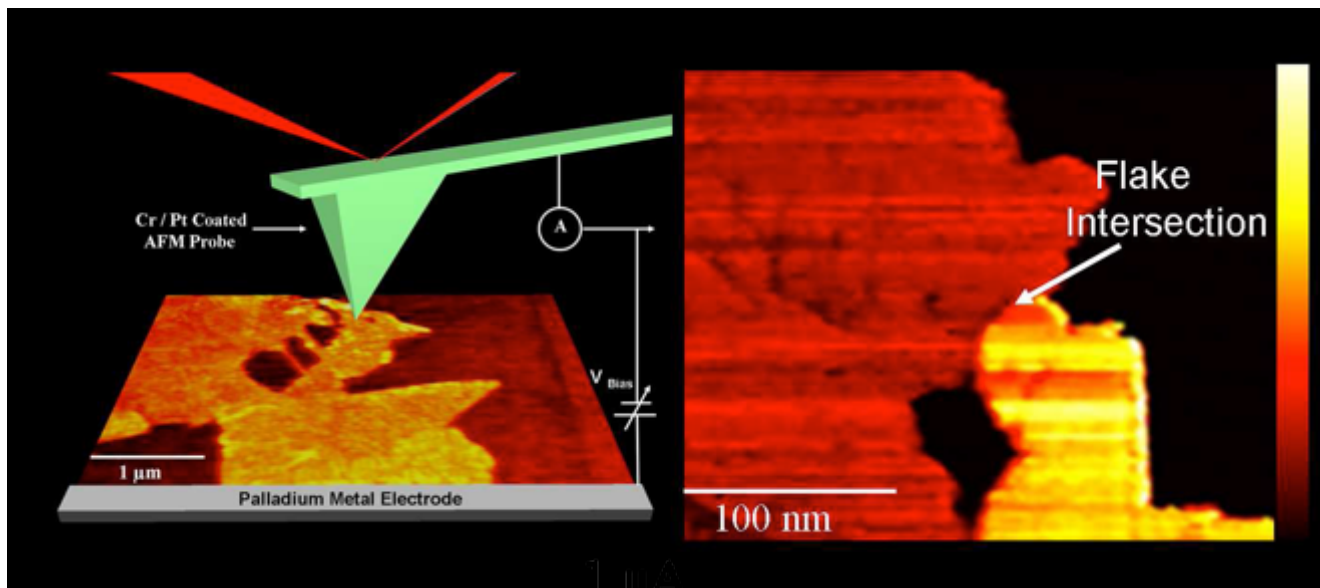
Structuring graphene devices



Kumar, S.; Peltekis, N.; Lee, K.; Kim, H. Y.; Duesberg, G. S.
Nanoscale Research Letters, 2011, 6, 390



Conductive AFM in graphene films

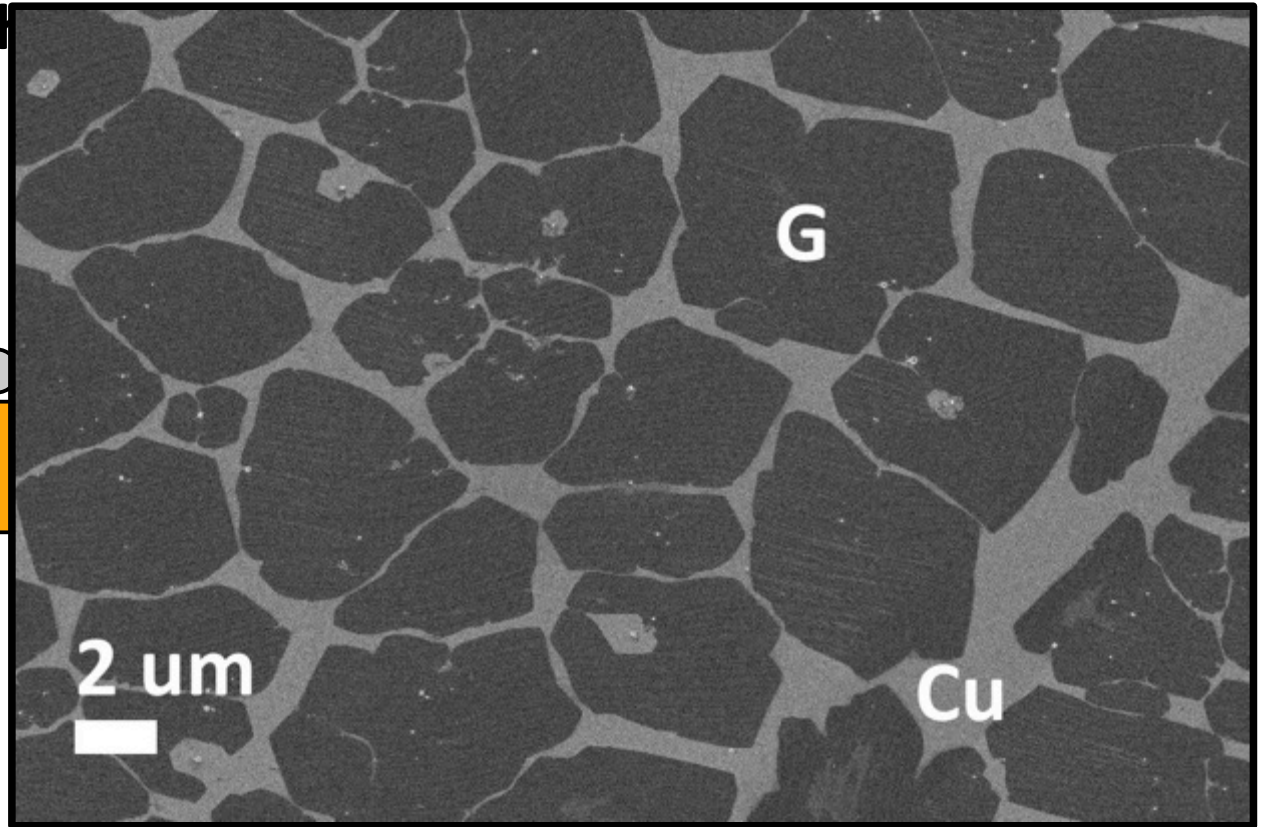
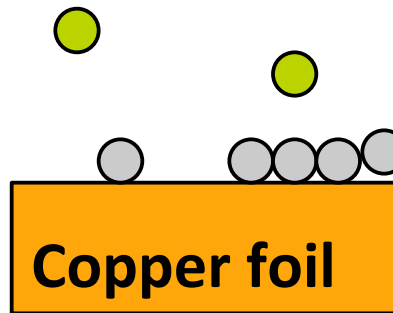


Graphene on Copper

Low solubility of carbon

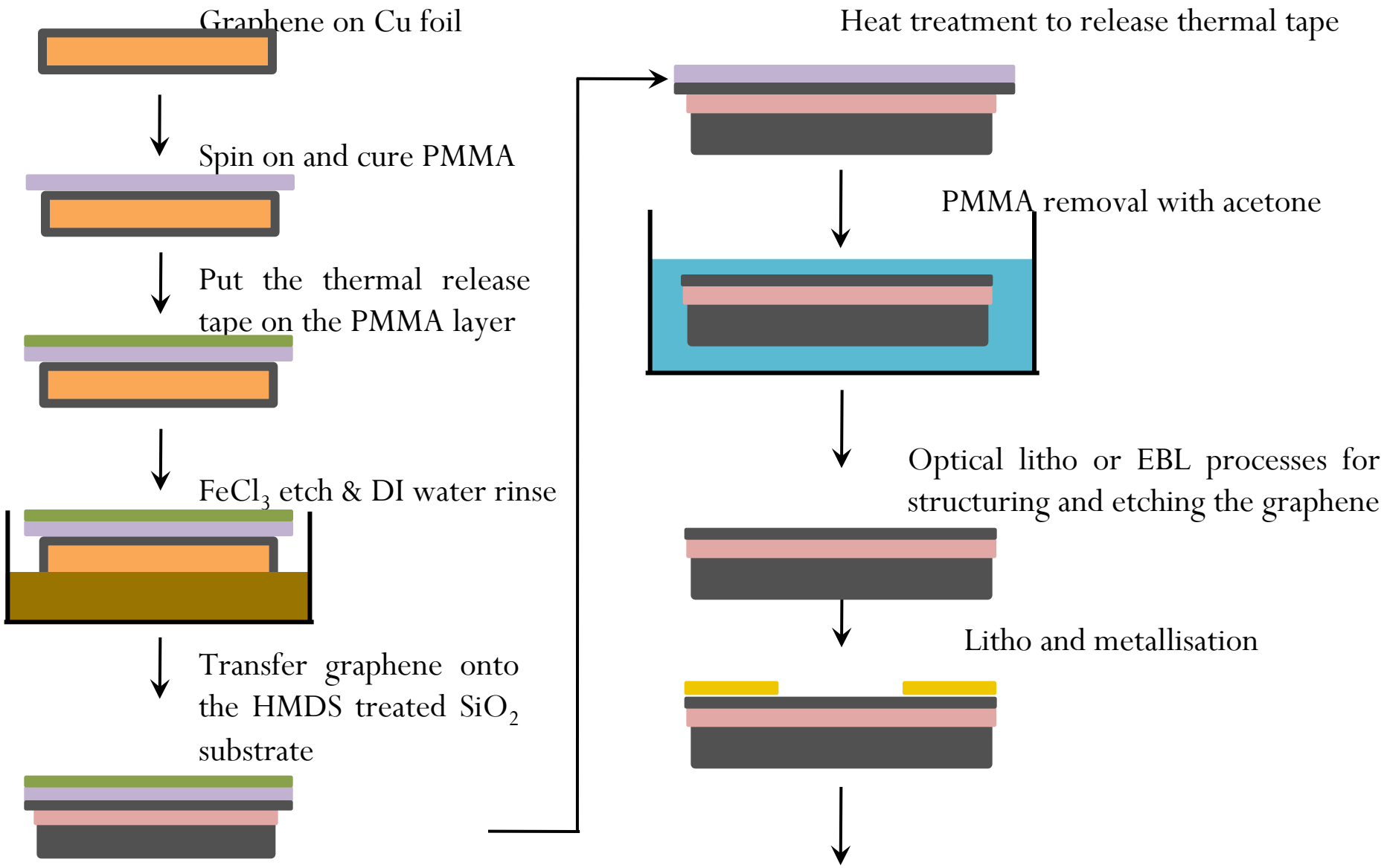
Less catalytic th

Lattice match





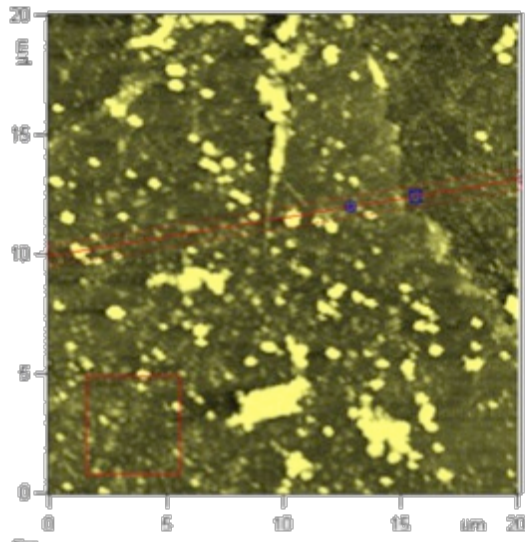
Polymer transfer technique for graphene



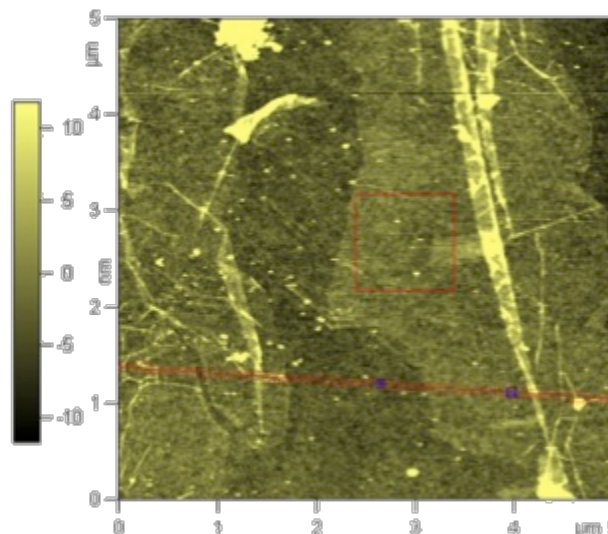


Analysis of plasma cleaned graphene

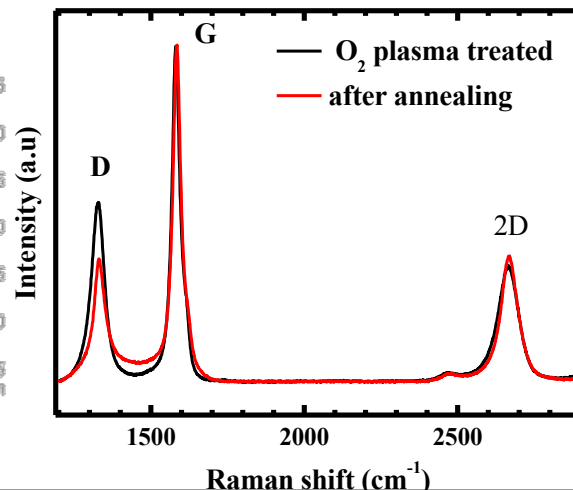
Graphene transferred with polymers is cleaned with remote plasma at low temps



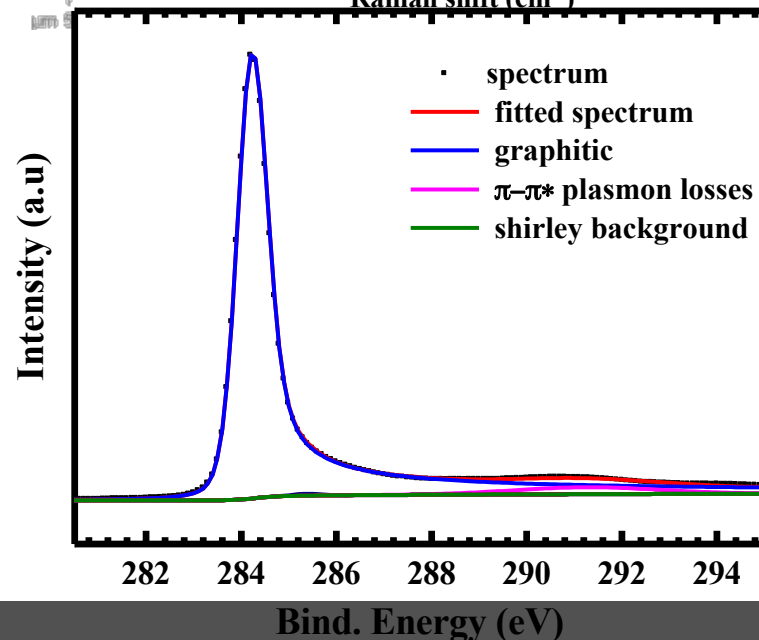
AFM Before



AFM After



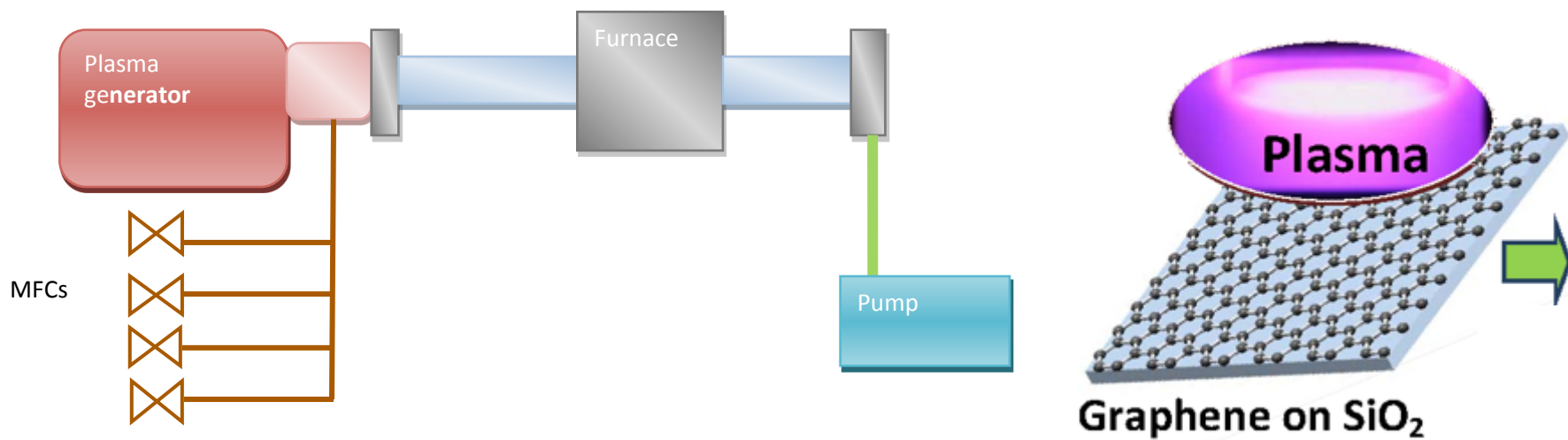
XPS C1s FWHM=0.68eV after annealing,
perfectly clean graphitic spectrum.



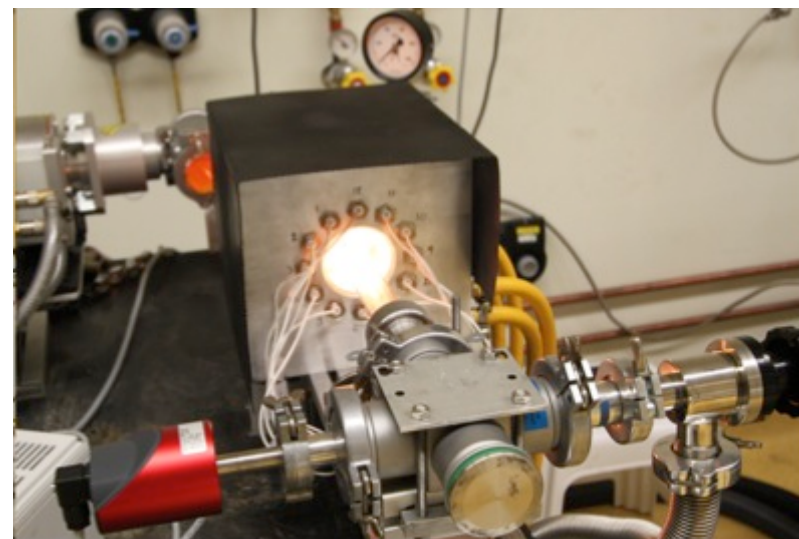
Peltekis, Duesberg et al. Carbon, accepted



Cleaning of graphene with plasmas

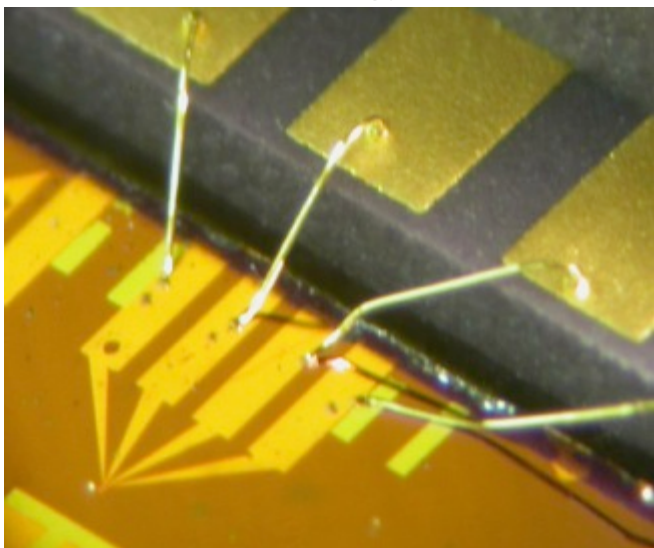
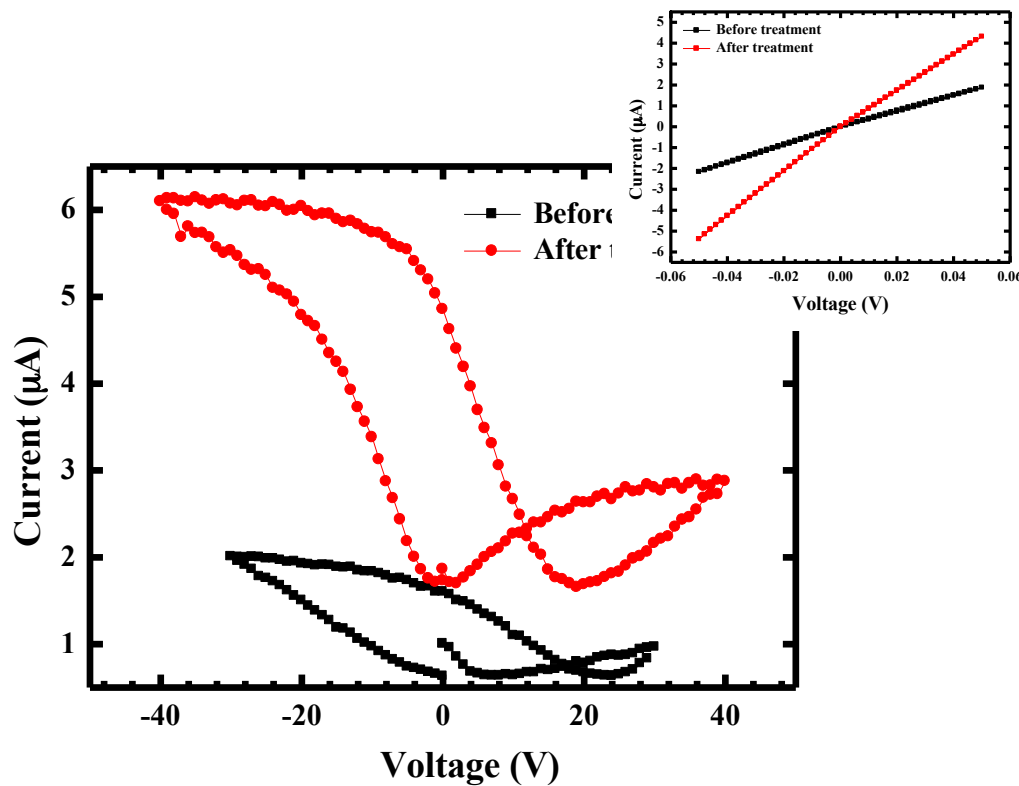
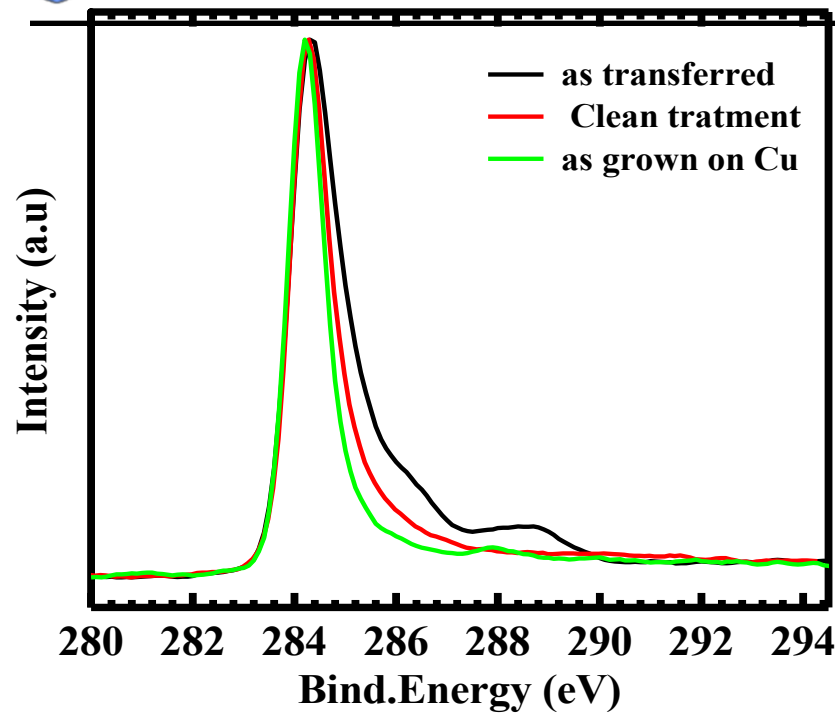


“Chemical” plasma by a remote source (R^3T TWR 2000-GEN, 400V) 1000W .
pressure of 1 torr flow rates of 100 sccm
Oxygen and Hydrogen





Cleaning of graphene with plasmas only

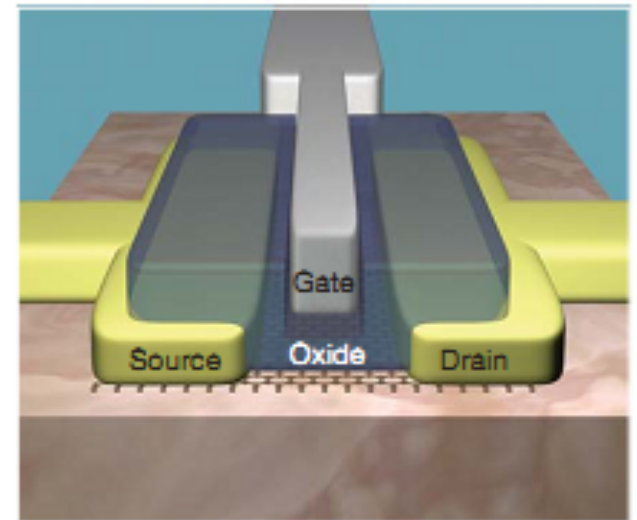
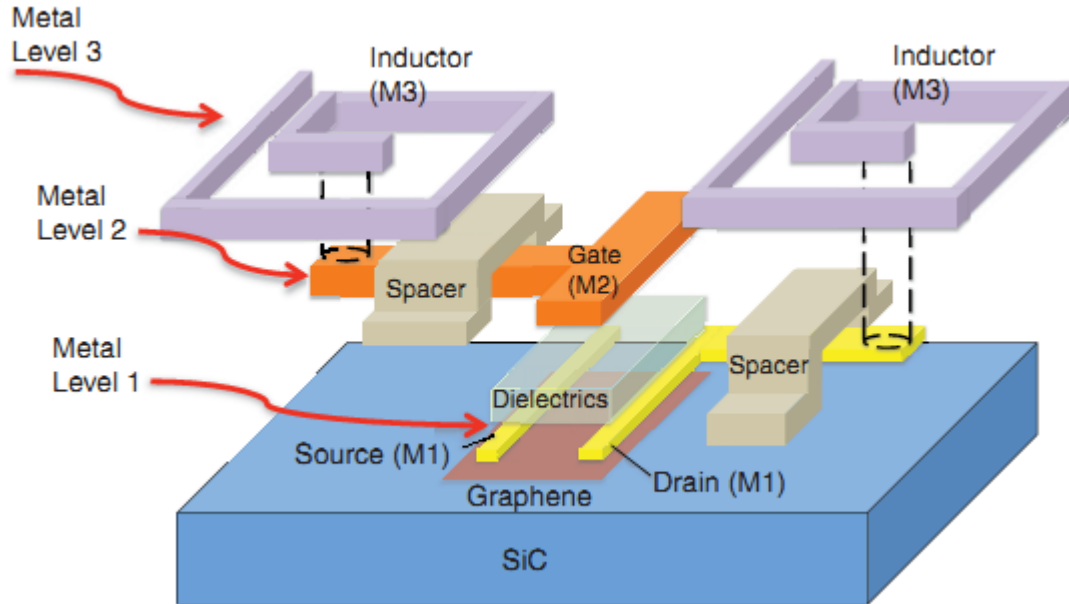


In-situ cleaning possible!
Conductivity and mobilities increased $\sim 200 \text{ cm}^2/\text{Vs}$ after plasma treatment
This applies to all graphene type samples

Peltekis, Duesberg et al. Carbon, accepted



Band gap ?



Avouris group IBM

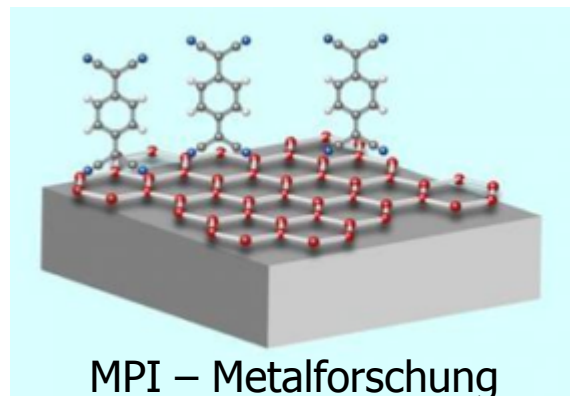
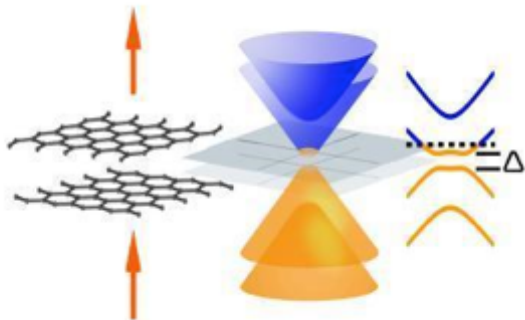


Band gap engineering in graphene

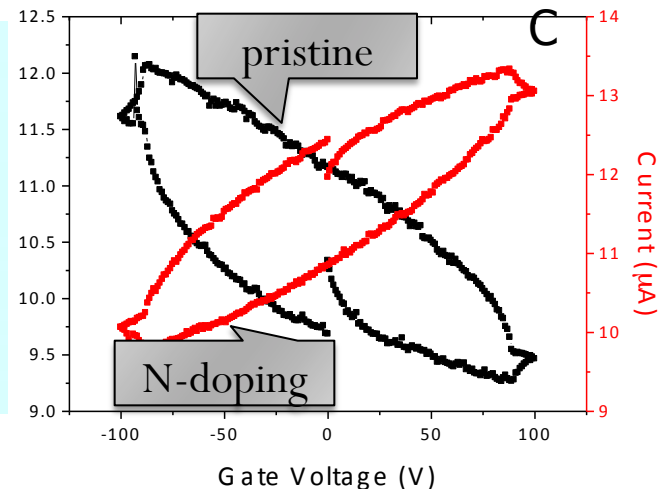


Double layers

Zhang et al. 2009 Nature

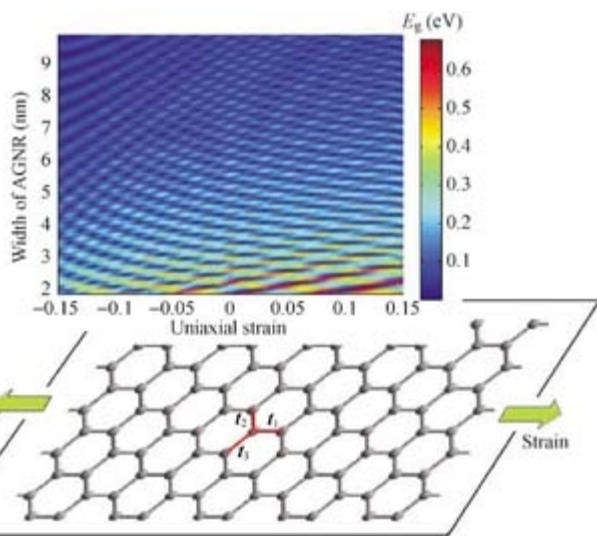


Functionalisation/ Doping



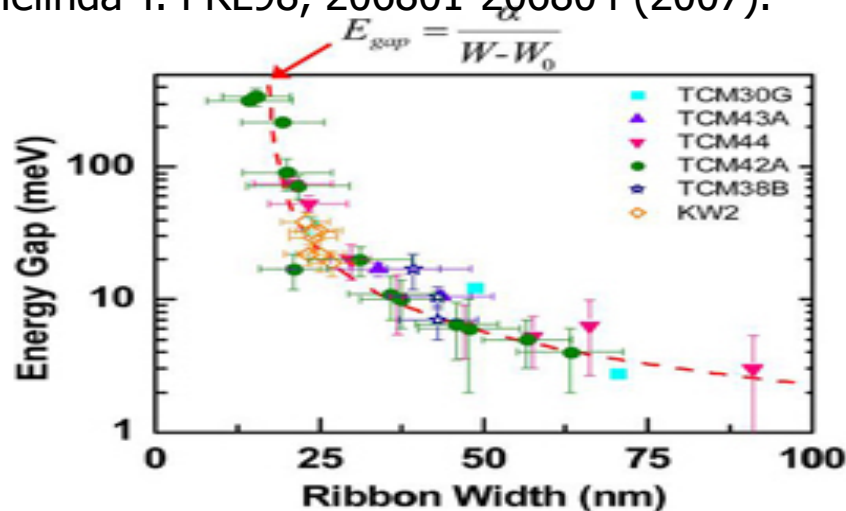
Stress

Lu, Nano Research 2009



Cut out/size effect

Melinda Y. PRL98, 206801-206804 (2007).





Graphene ribbons – chemical routes

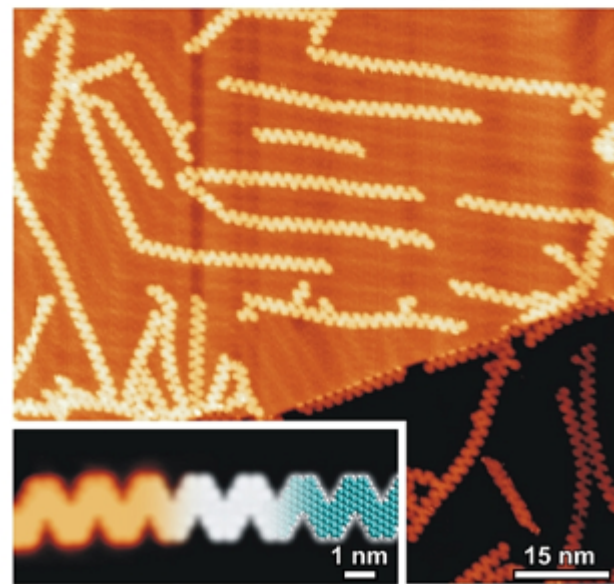
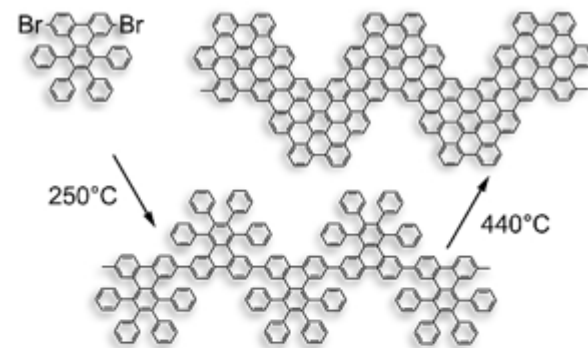
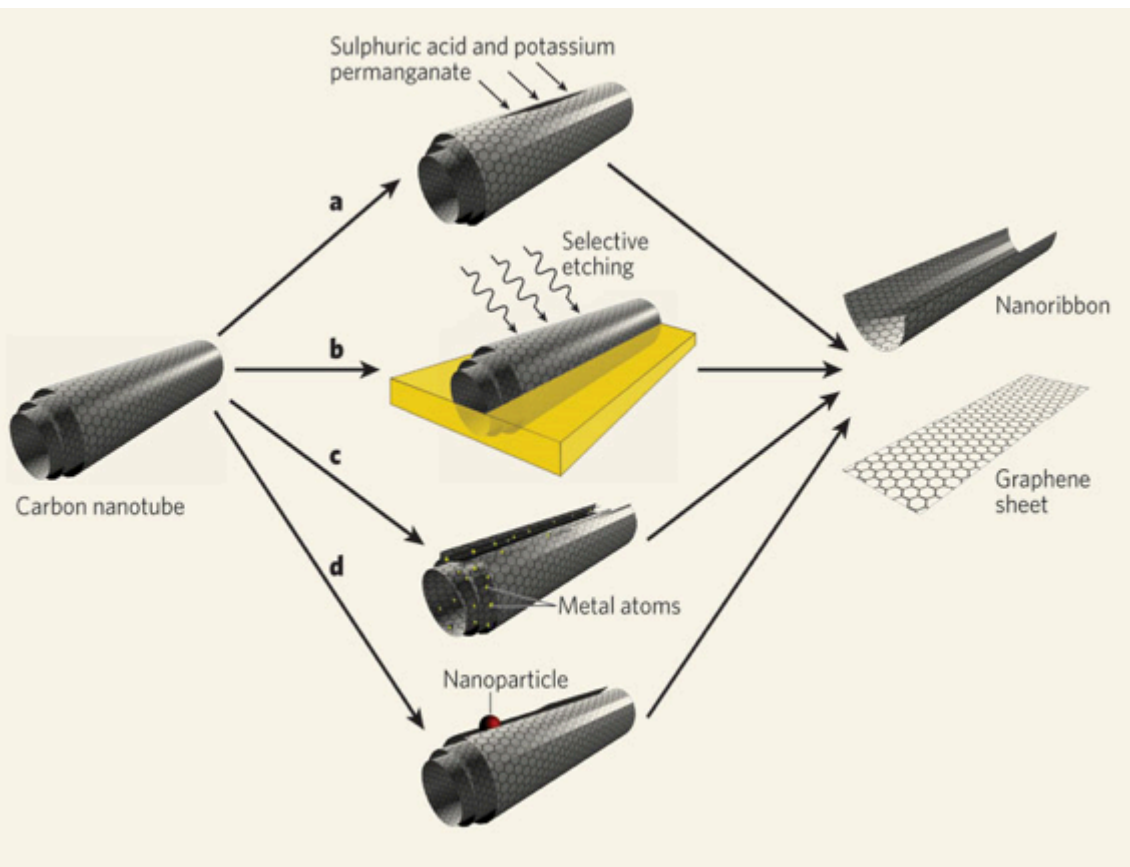


Materials science: Nanotubes unzipped

Mauricio Terrones

Nature 458, 845-846(16 April 2009)

Atomically defined structures!

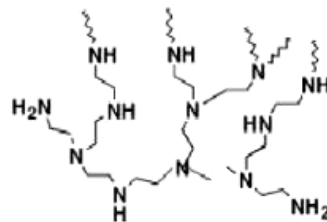
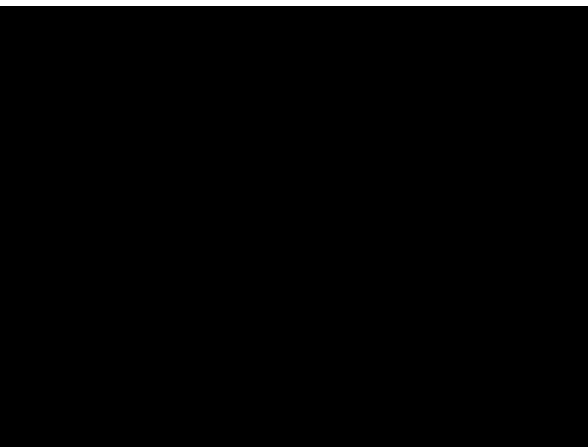
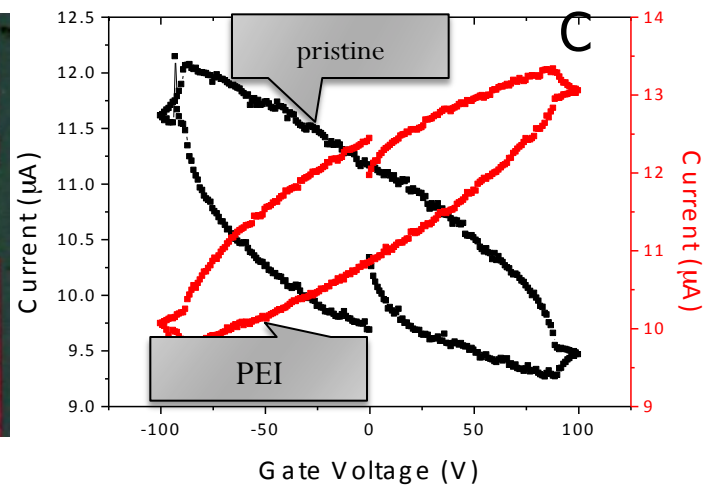
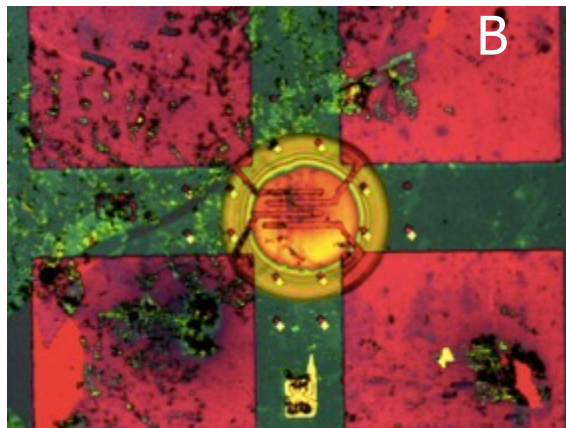
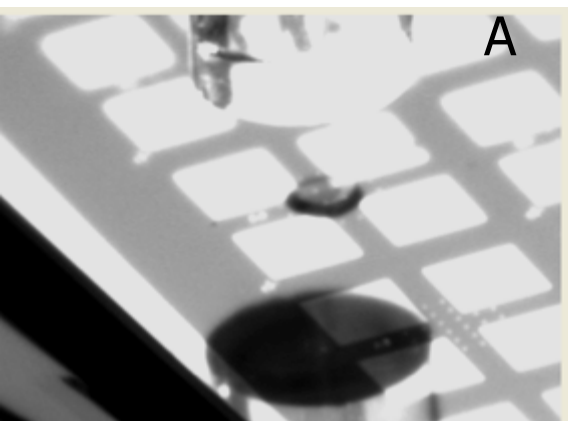


J. Cai, et al. Nature, 2010

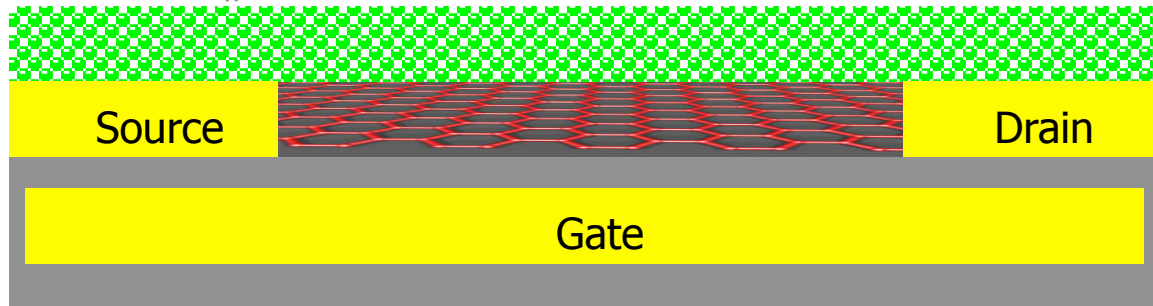
Same or even more problems as with nanotubes



Top coated graphene Fets



n-Doping : Polyethylenimine (PEI)

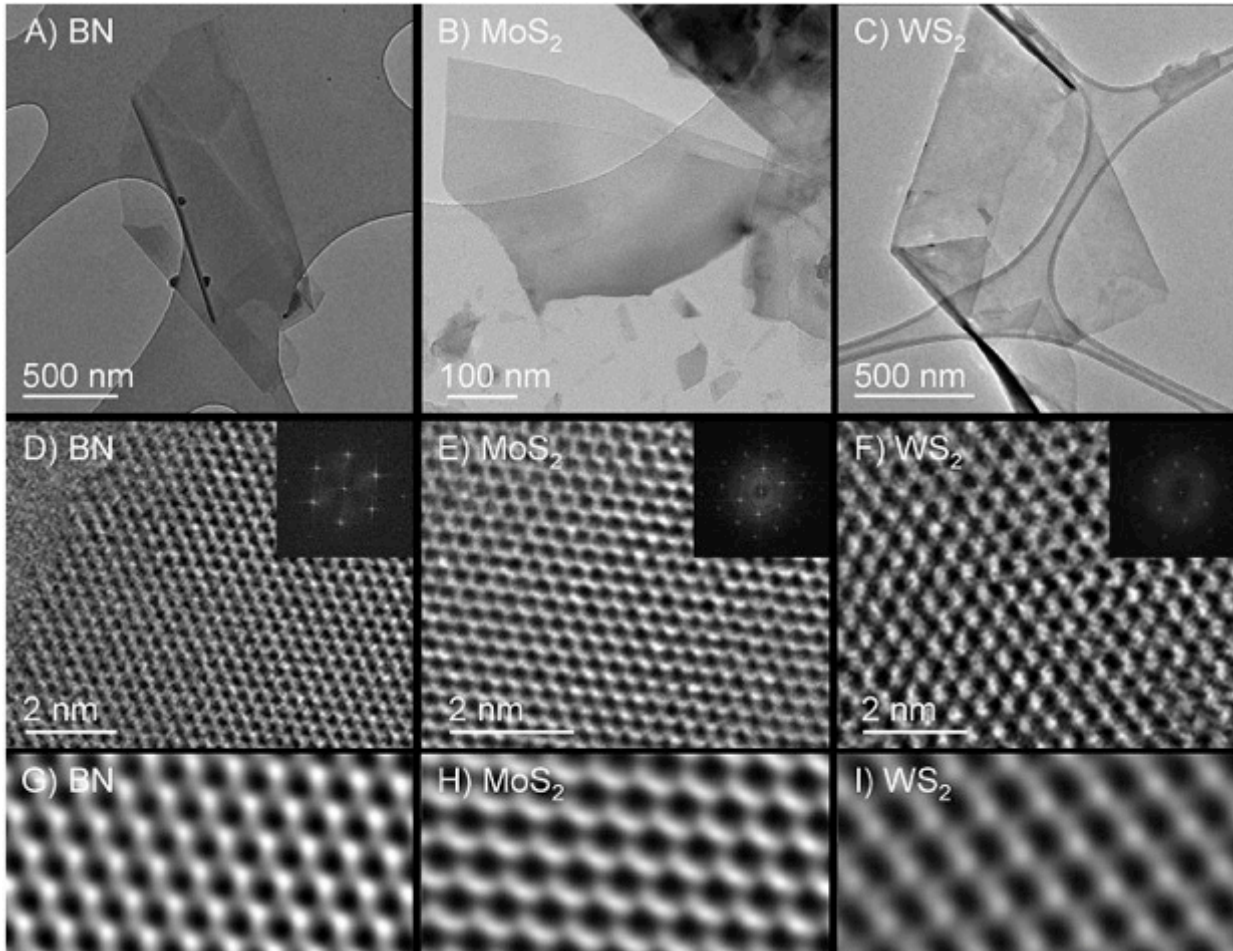




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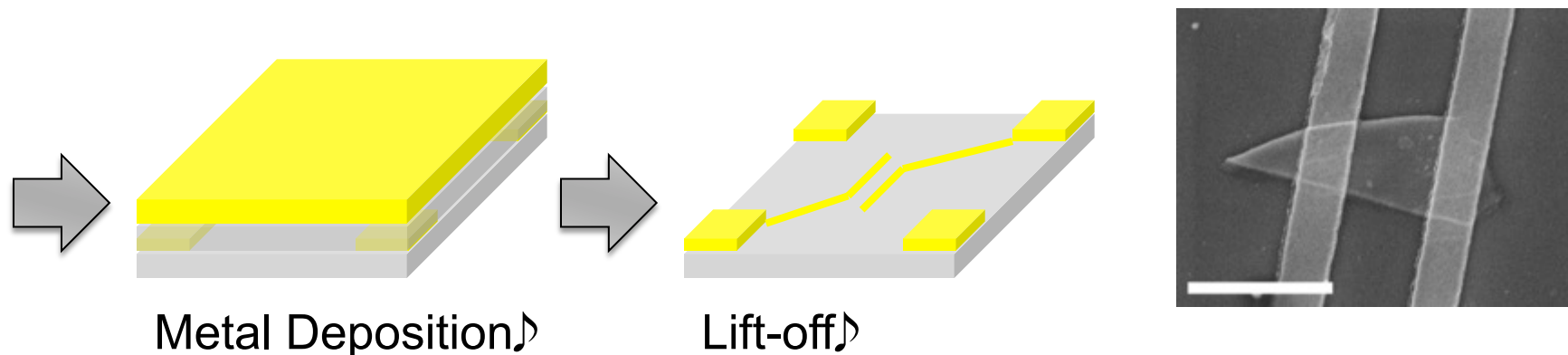
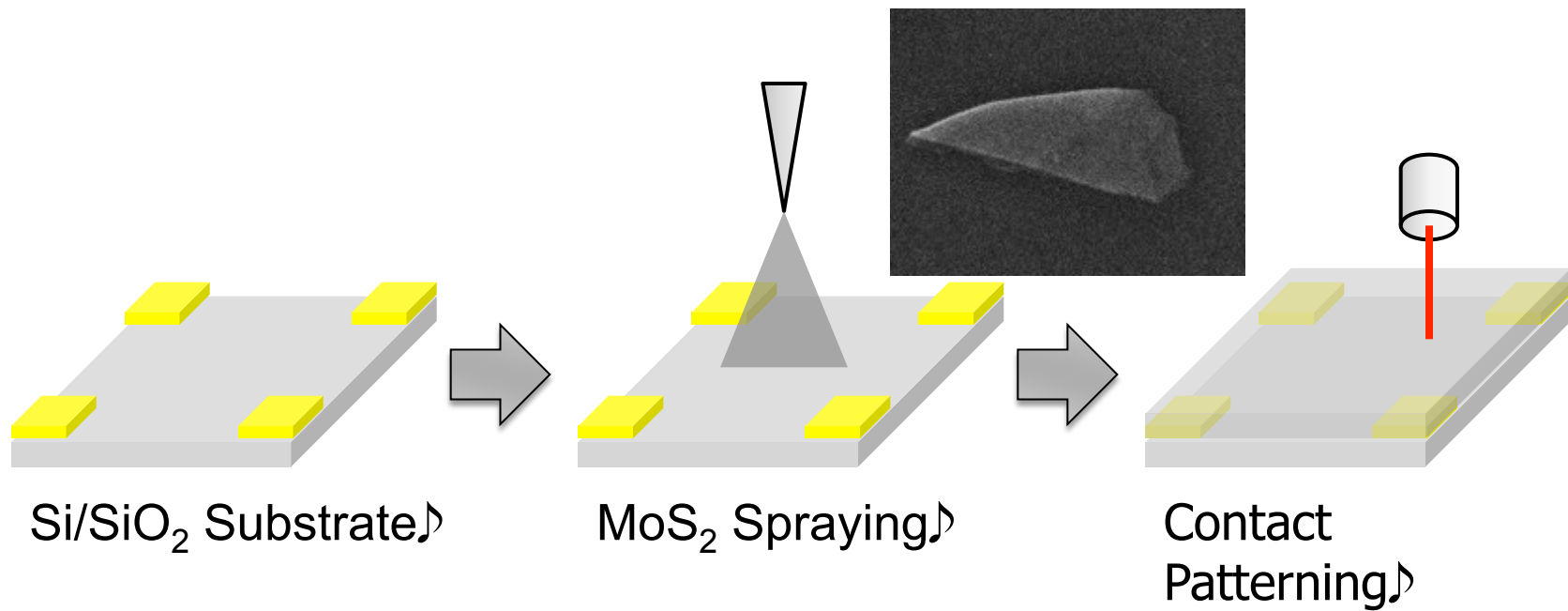


Layered compounds such as MoS_2 , WS_2 , MoSe_2 , MoTe_2 , TaSe_2 , NbSe_2 , NiTe_2 , BN , and Bi_2Te_3 can be efficiently dispersed (also topological insulators?!)

Jonathan N. Coleman, Hye-Young Kim, Kangho Lee, Gyu Tae Kim, Georg S. Duesberg, Nicolosi, et al, "Two-Dimensional Nanosheets Produced by Liquid Exfoliation of Layered Materials", **Science**, 568-571, 2011

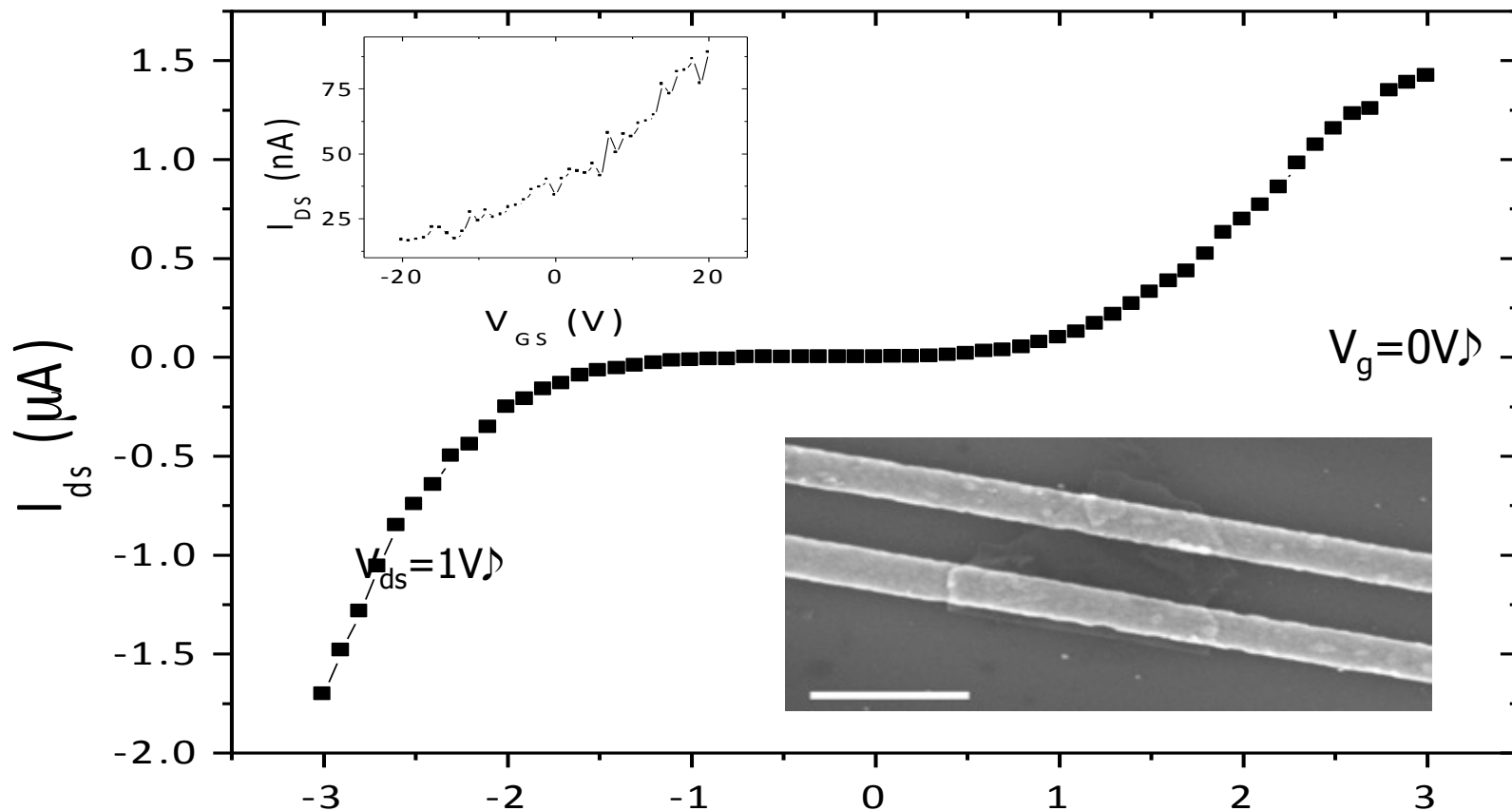


Contacting individual MoS₂ flakes



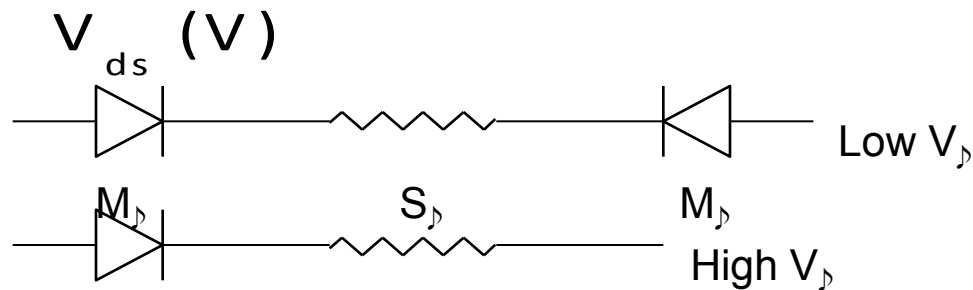


E-beam contacted MoS₂ flake



Up to $\mu = 195 \text{ cm}^2/\text{Vs}$ can be extracted based a model taken into thermal field emission (MSM). (similar to B. Radisavljevic, A. Kis, Nature Nano 2011)

Lee, Kim, Duesberg et al. Adv Mater., 2011





Outline

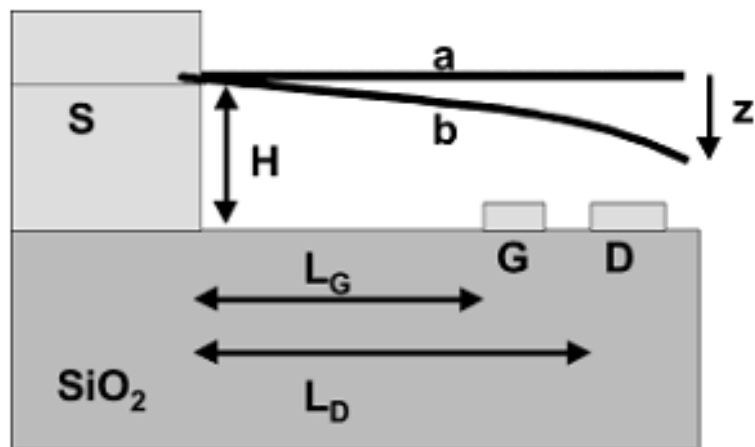


- ▶ Carbon Nano-structures: Applications in microelectronics
- ▶ Vertical Carbon devices
- ▶ Graphene Processing
- ▶ Other 2D Materials
- ▶ Carbon NEMS?
- ▶ Conclusions

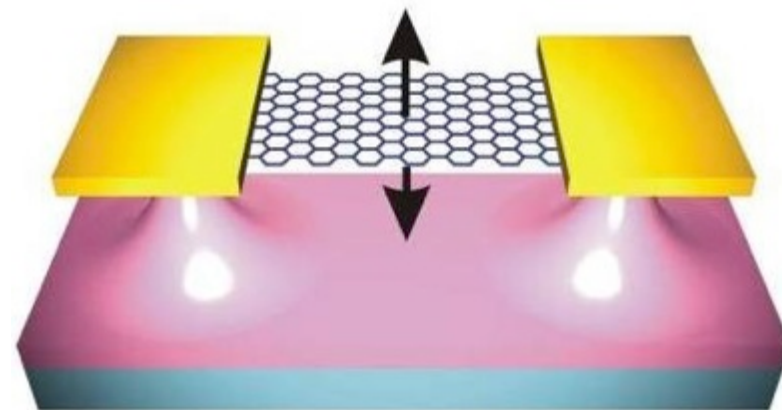


CNT relay and graphene resonator

- High on/off ration
- Low power
- High speed
- Carbon stable and light = high Q factors



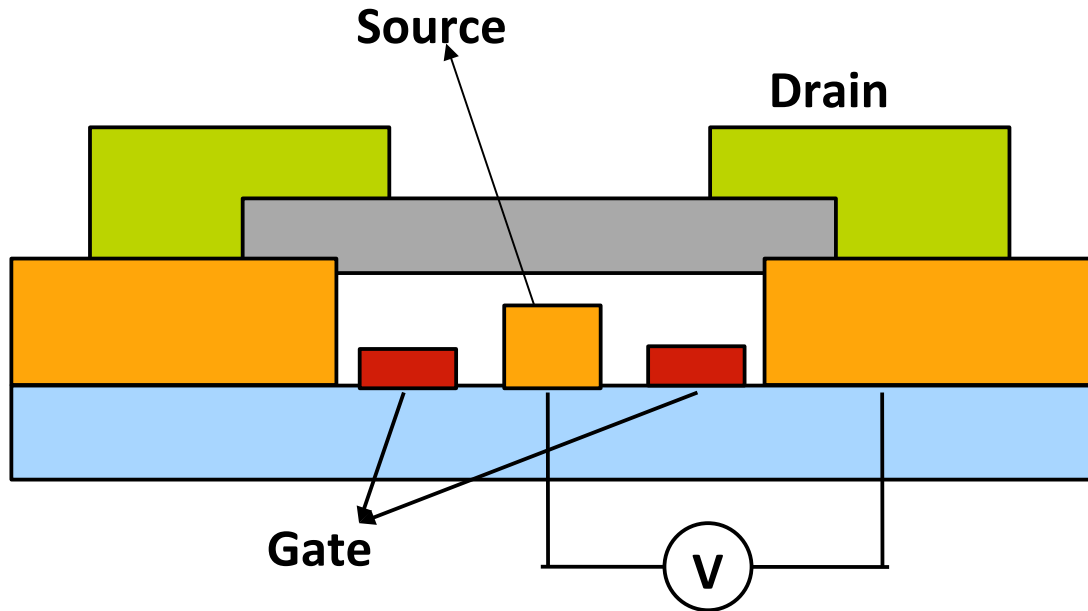
Nanorelay, Lee et al.
Nanoletters 2003



Bachthold et al. 2009



Micromechanical switch

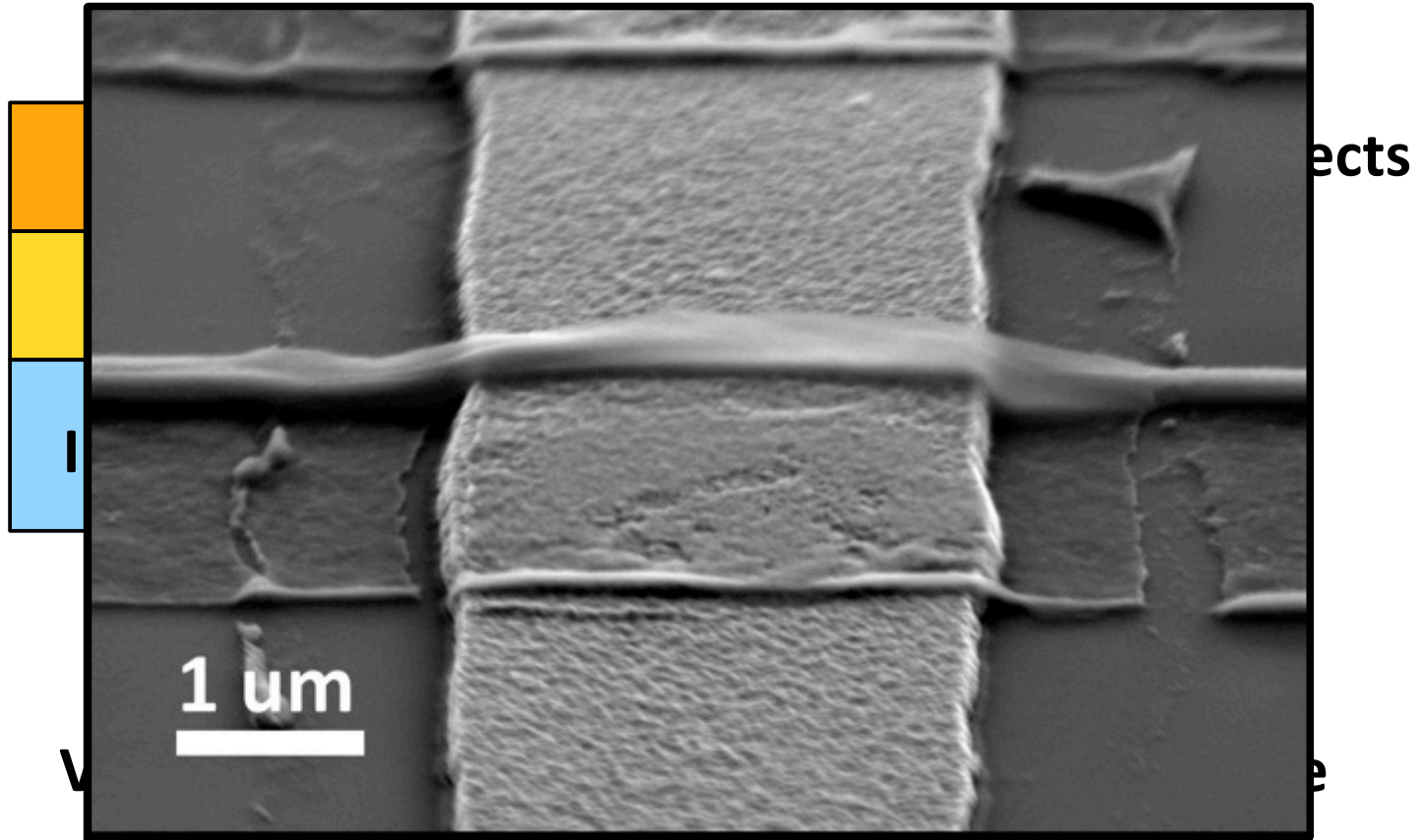


Advantages

- very high on-off ratios
- can have very high operating frequencies
- can be used with loaded graphene for sensing applications
- robust in extreme environments

Kumar et al. unpublished

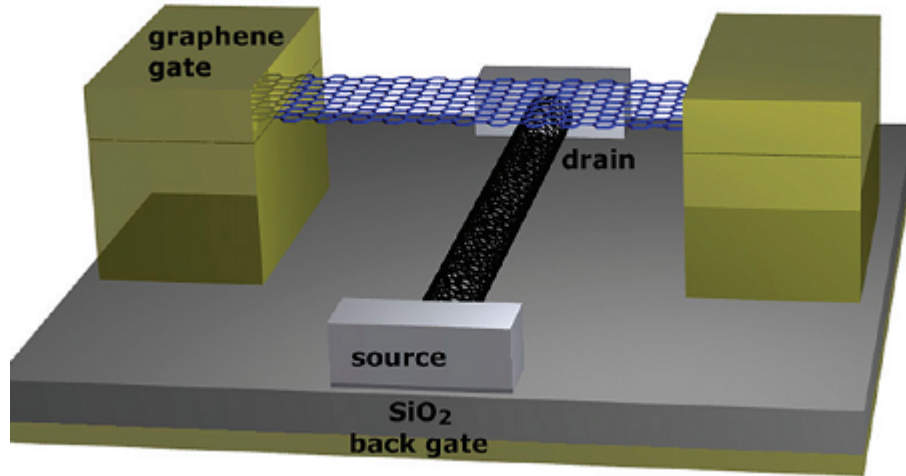
Suspended graphene



Surface tension breaks G → use critical point dryer

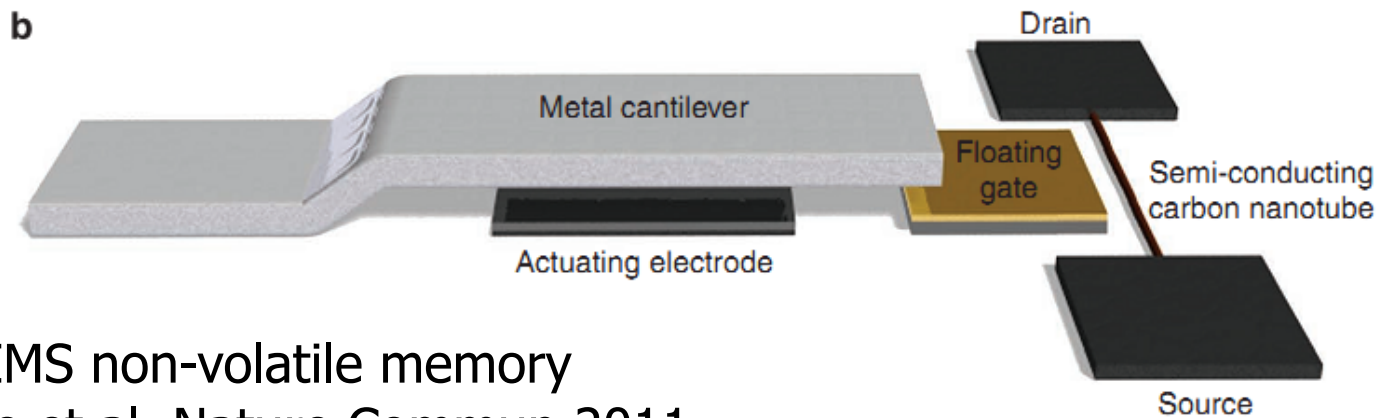


Carbon NEMS devices



Overcome Subthreshold limit

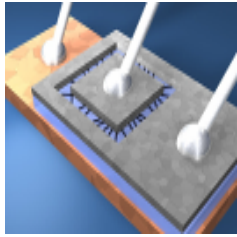
Moving gate,
Svenson et al. Nanoletters 2011



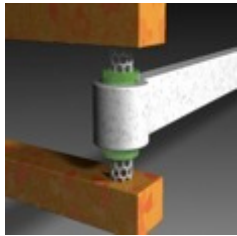
NEMS non-volatile memory
Lee et al. Nature Commun 2011



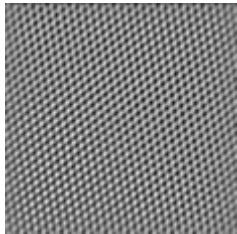
Conclusions



Lateral carbon FETs may have application as power transistors or in flexible, transparent electronics, sensors etc. (More than Moore)



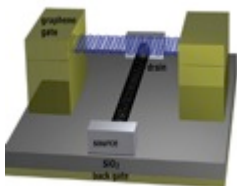
Vertical FET face integration challenges (high k , contact engineering, Growth of CNTs) but have a lot of potential



Graphene can be synthesized and processed on the large scale but band gap engineering/passivation is crucial – potential for Spintronics and NEMS



New 2D Materials have a lot of potential for electronics and energy harvesting



Carbon NEMS have superior properties



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Collaborators

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Prof. Coleman – TCD

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